

Circuitos Digitales



Niveles de tensión
discretos

Circuitos Digitales
Binarios

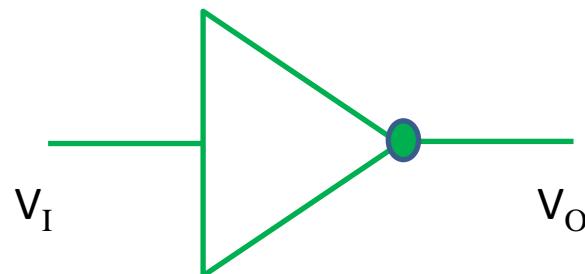


Dos niveles de
tensión

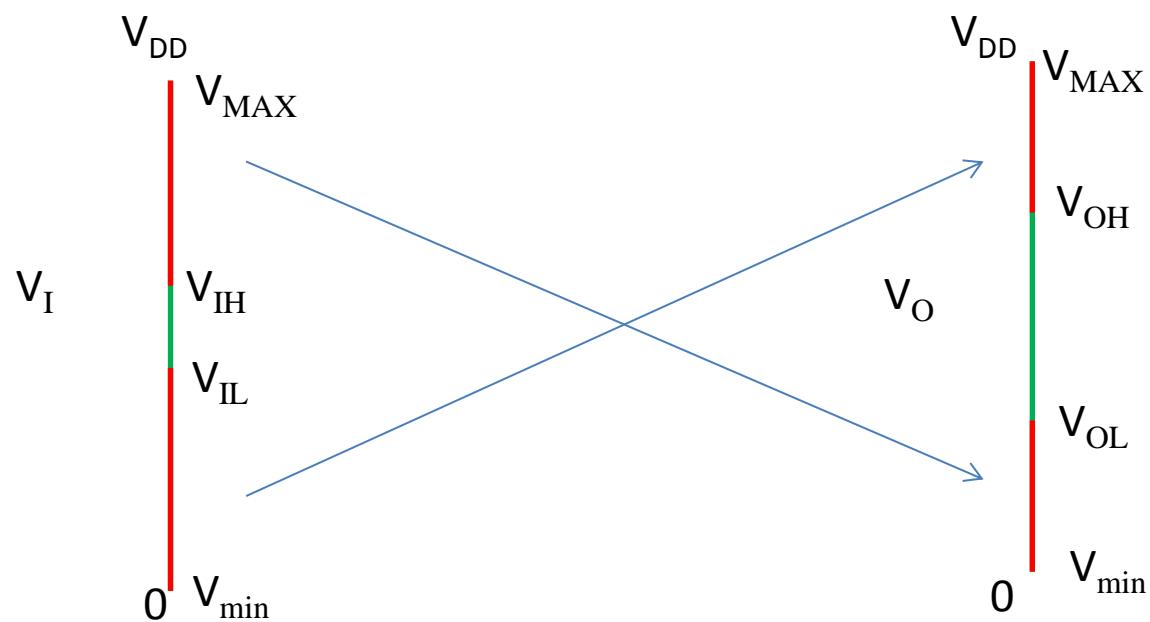
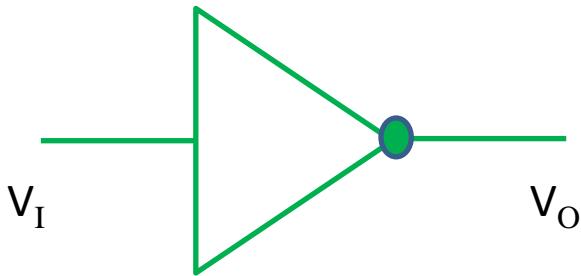
$V_H \rightarrow 1$

$V_L \rightarrow 0$

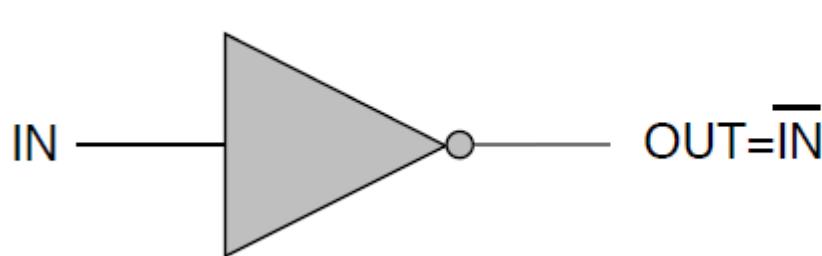
Circuito Inversor



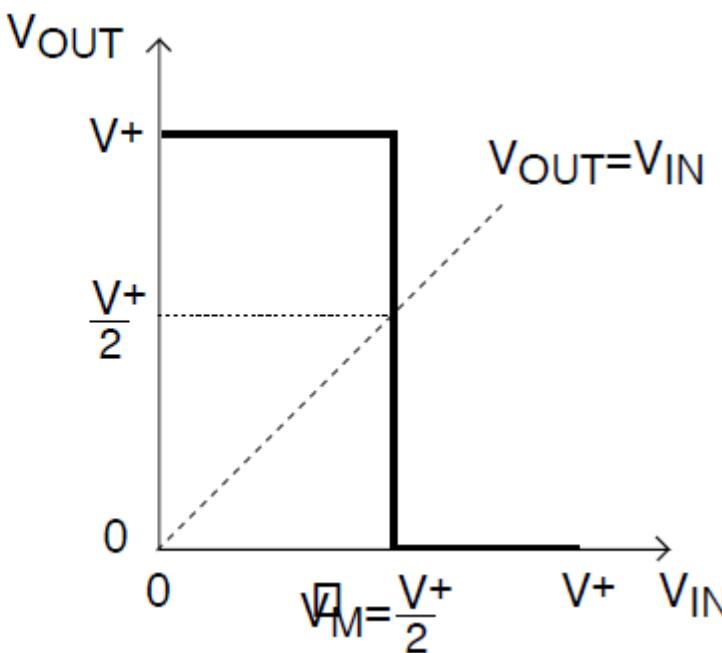
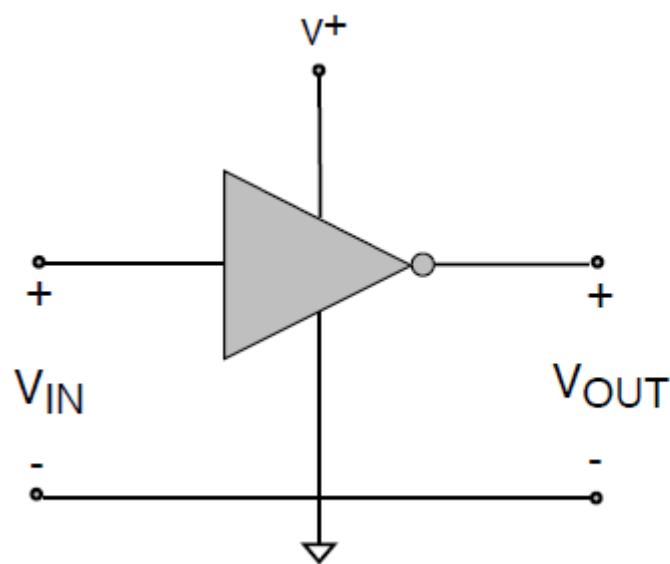
V_I	V_O
1	0
0	1



INVERSOR IDEAL



IN	OUT
0	1
1	0



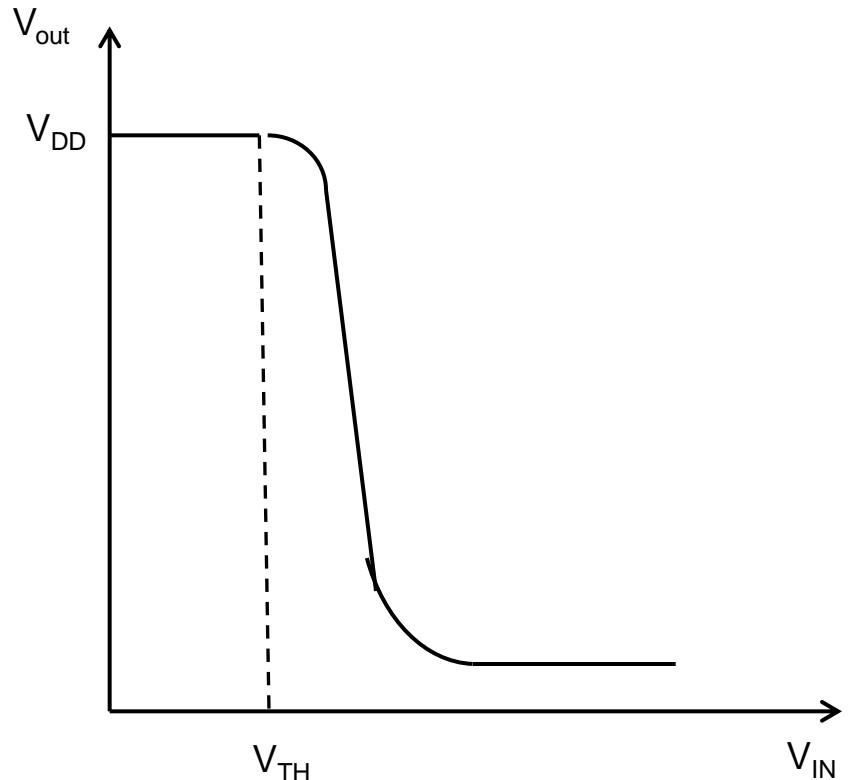
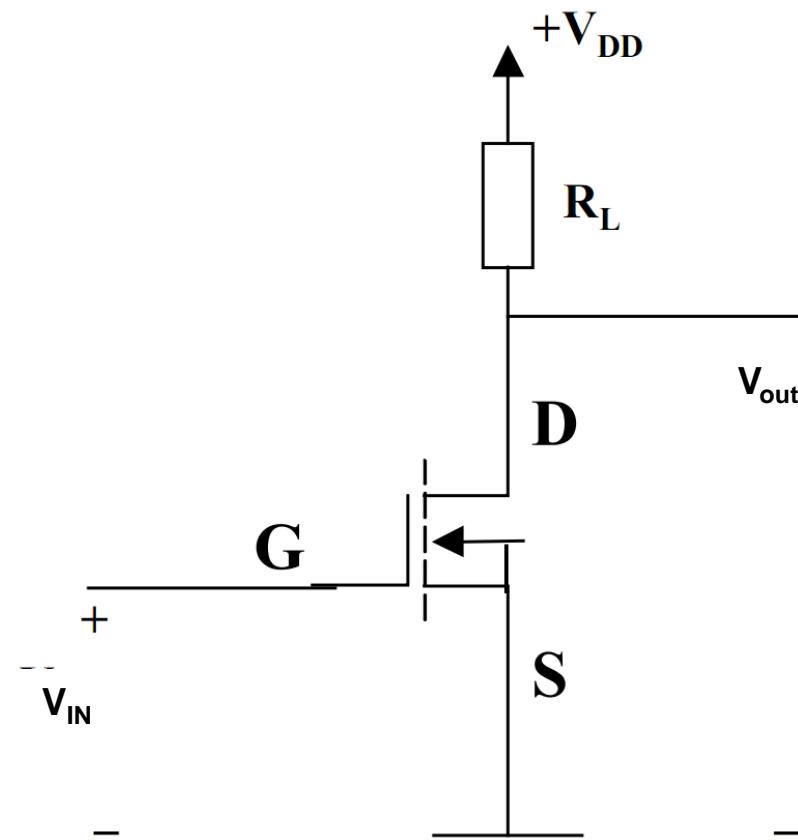
$$0 \leq V_{IN} < V_M \rightarrow V_O = V^+$$

$$V_M \leq V_{IN} < V^+ \rightarrow V_O = 0$$



$V_M \rightarrow$ Umbral lógico o Punto de transición

INVERSOR NMOS



$$0 < V_{IN} < V_{TH}$$

MOS → CORTADO

$$V_0 = V_{DD}$$

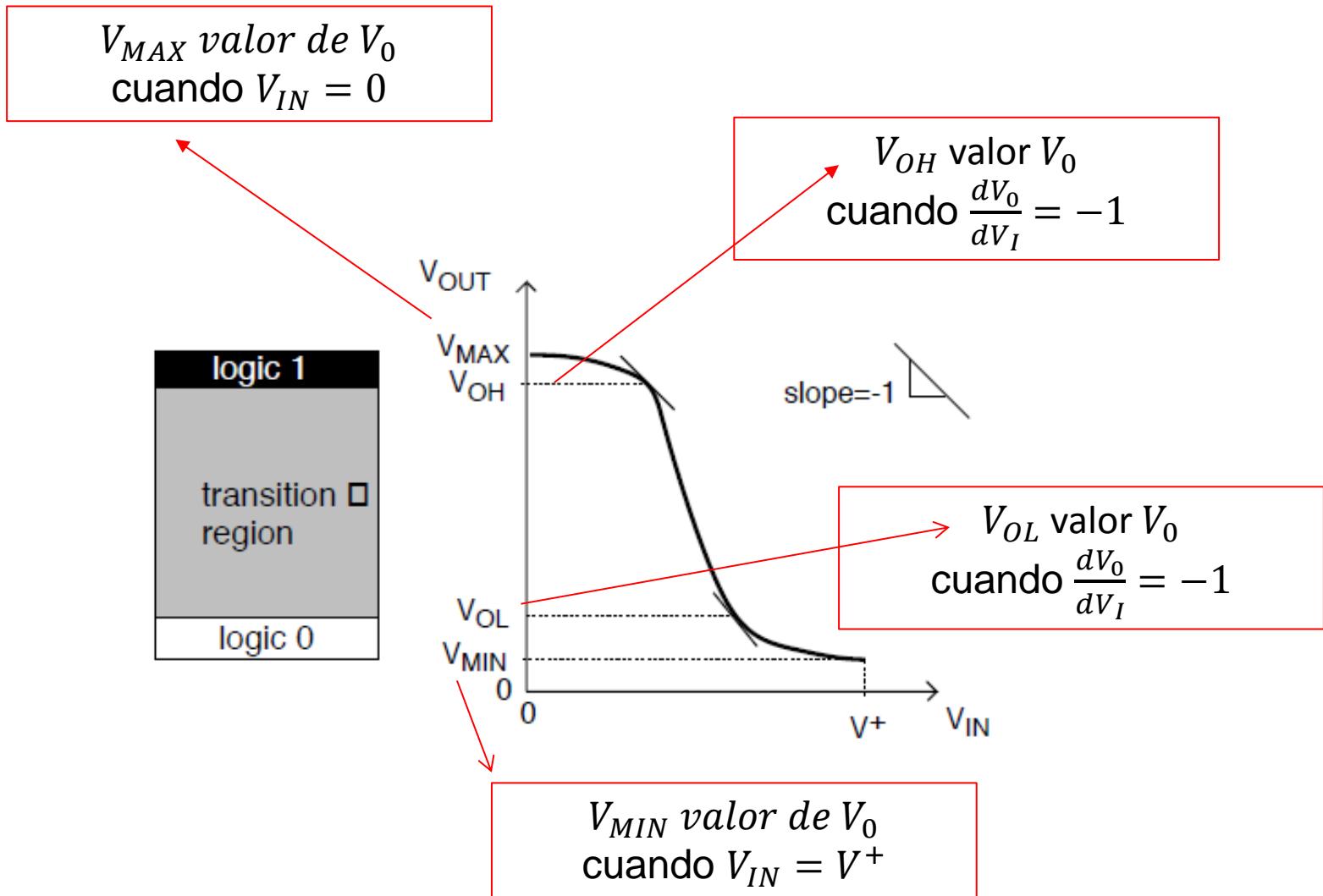
$$V_{TH} < V_{IN}$$

MOS → CONDUCE

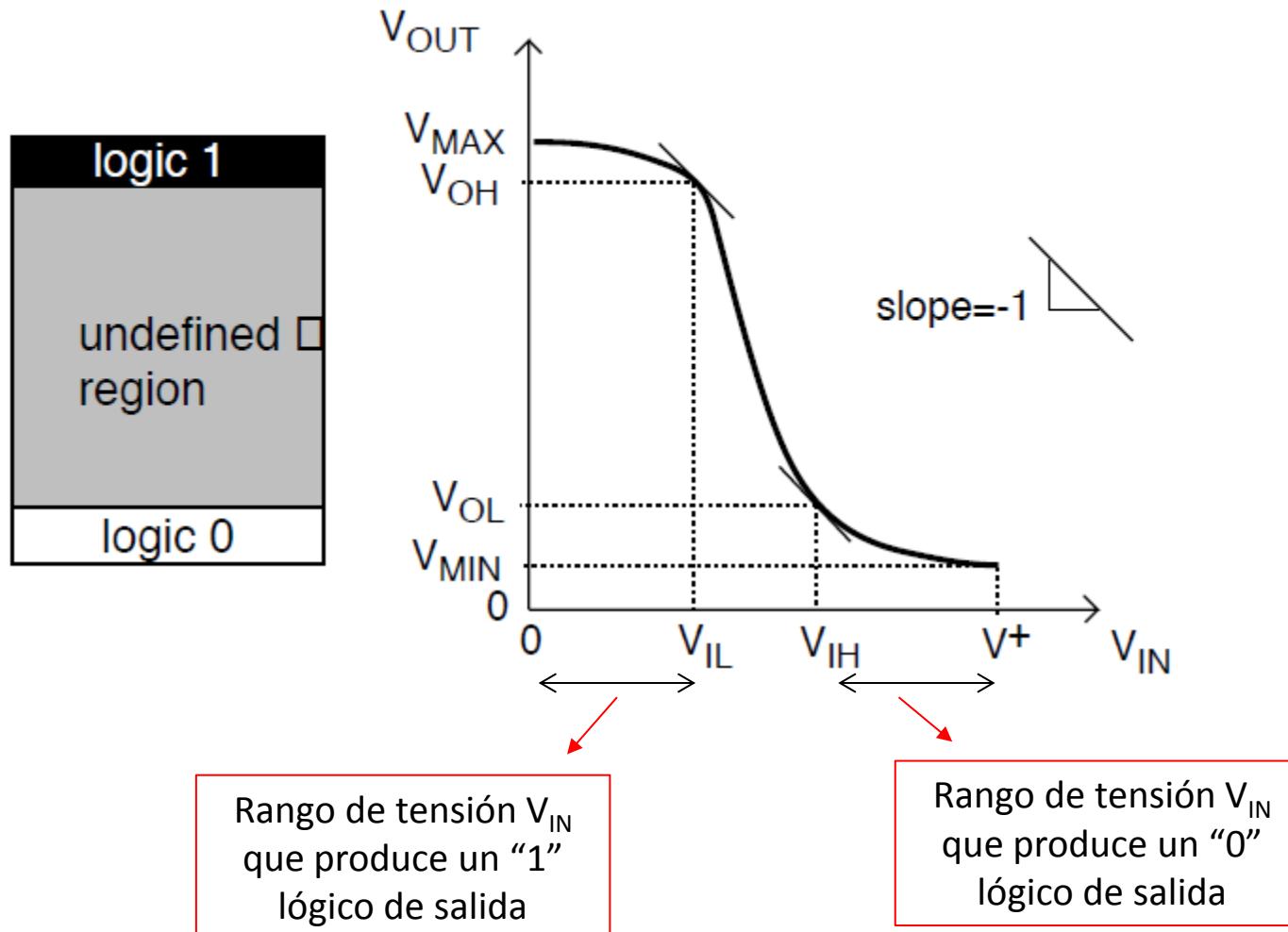
$$V_0 = V_{DD} - I_{DS} \times R_L$$

INVERSOR REAL

Niveles Lógicos

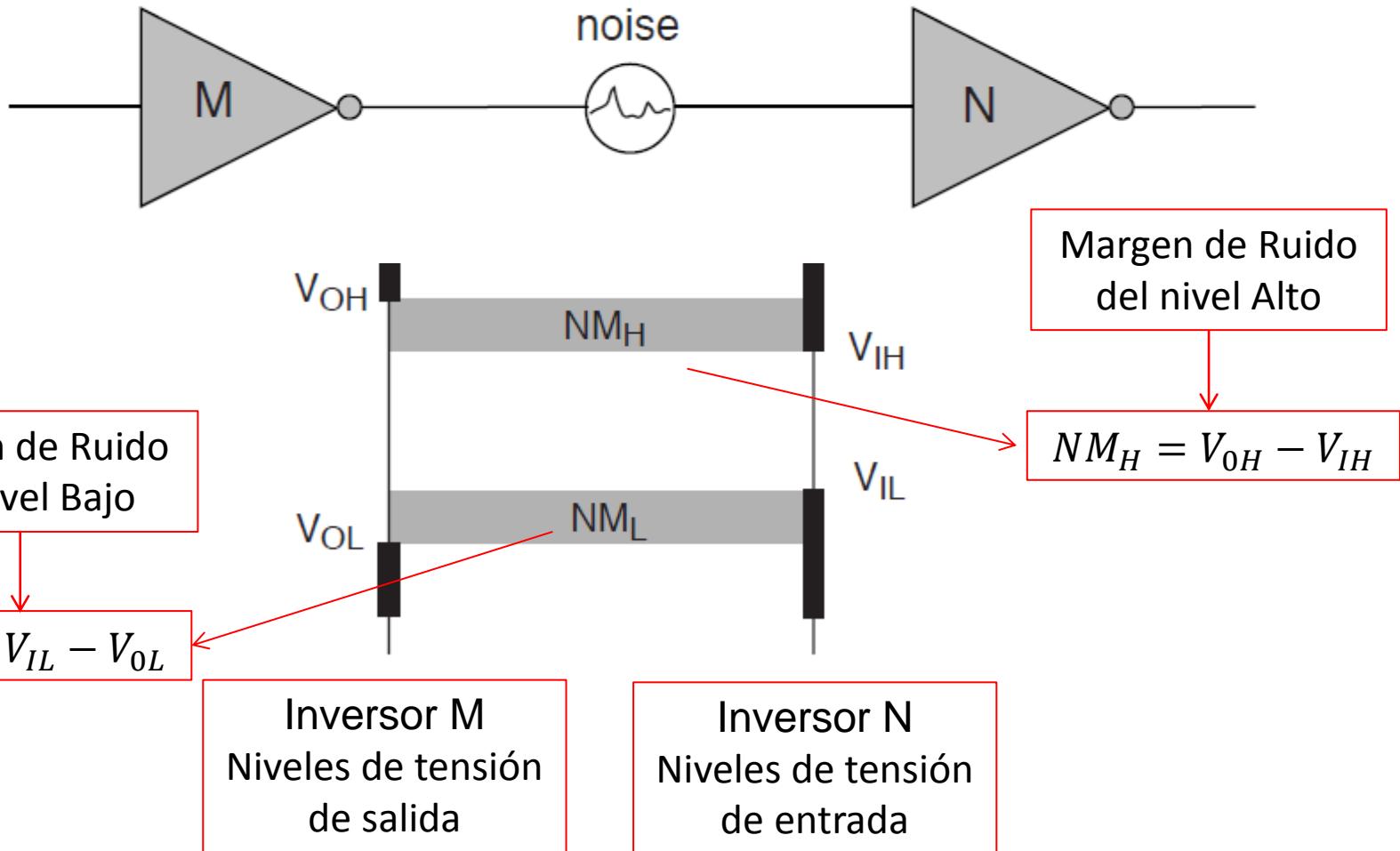


INVERSOR REAL

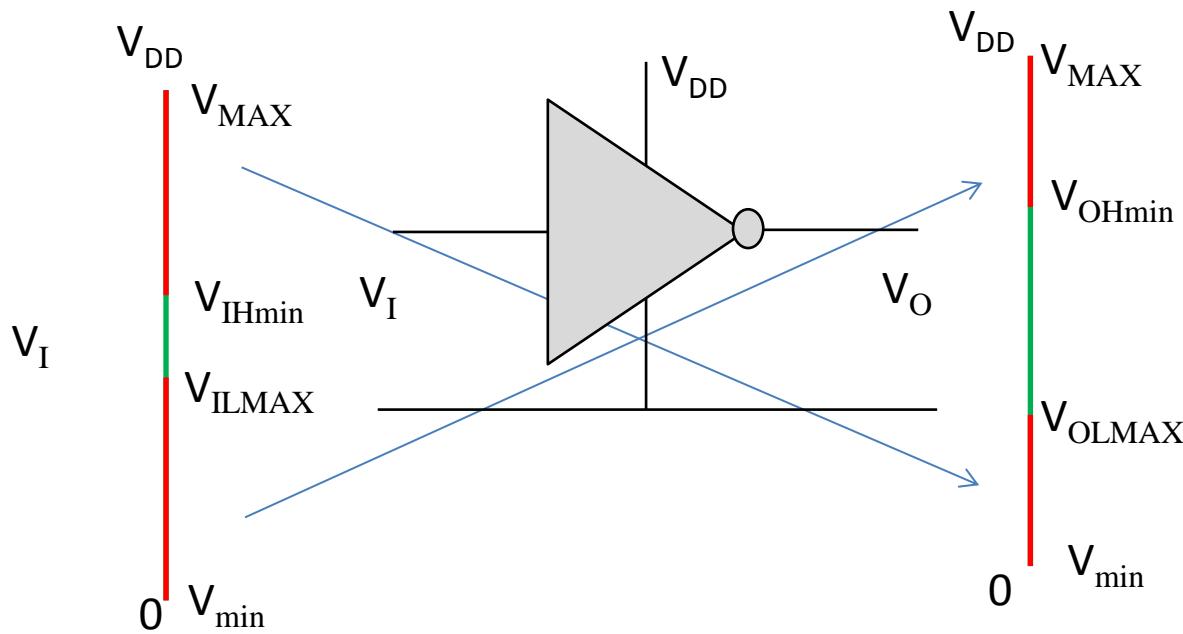


INVERSOR REAL

Margen de ruido



El margen de ruido se calcula tomando la peor situación



Para conectar dos inversores en cascada

Nivel bajo peor caso

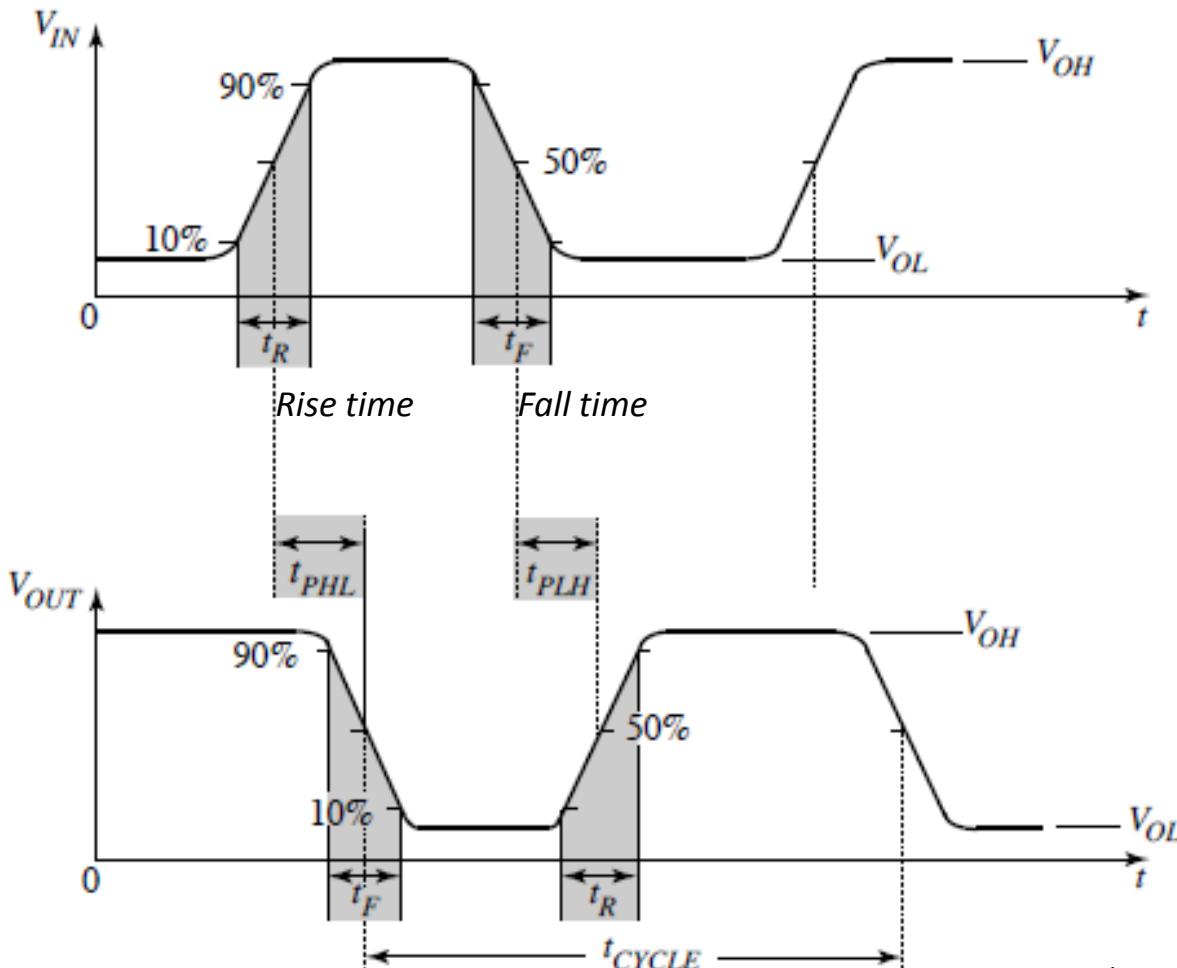
$$V_{OLMAX} \leftrightarrow V_{IILMAX}$$

Nivel alto peor caso

$$V_{0Hmin} \leftrightarrow V_{IHmin}$$

INVERSOR REAL

Tiempos de conmutación



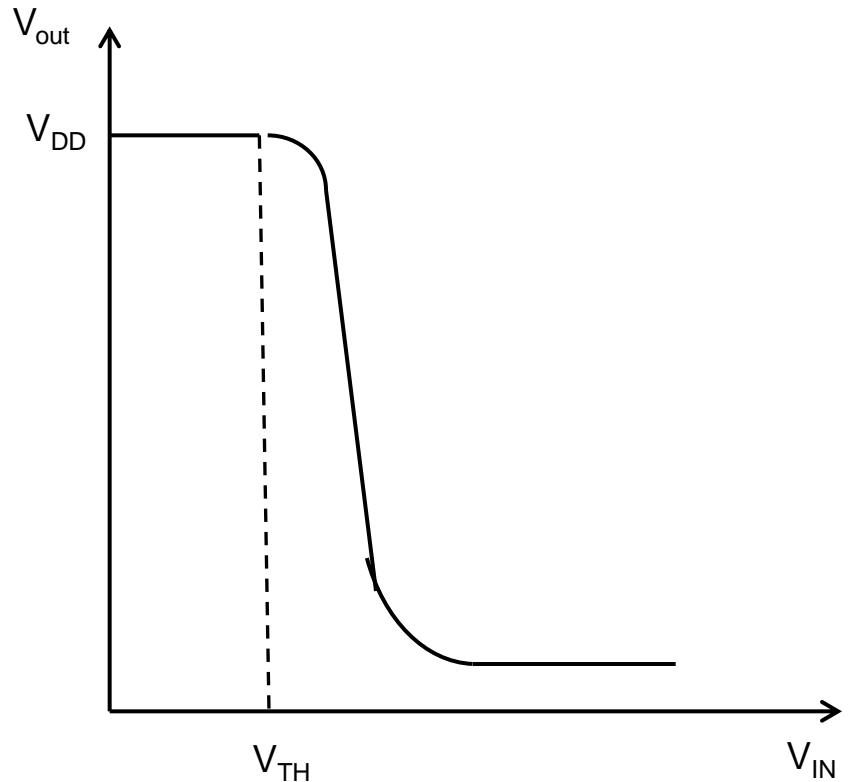
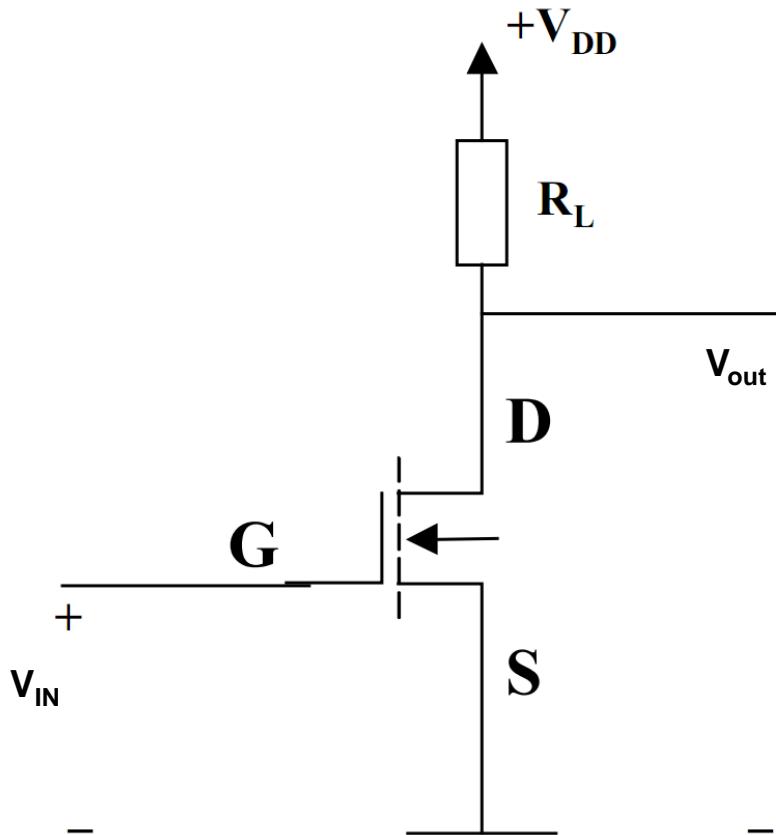
$t_{PHL} \rightarrow$ tiempo de conmutacion de alto a bajo

$t_{PLH} \rightarrow$ tiempo de conmutacion de bajo a alto

$$t_P = \frac{1}{2}(t_{PHL} + t_{PLH})$$

Retardo
de propagación

INVERSOR NMOS



$$0 < V_{IN} < V_{TH}$$

MOS → CORTADO

$$V_0 = V_{DD} \rightarrow V_H$$

$$V_{TH} < V_{IN}$$

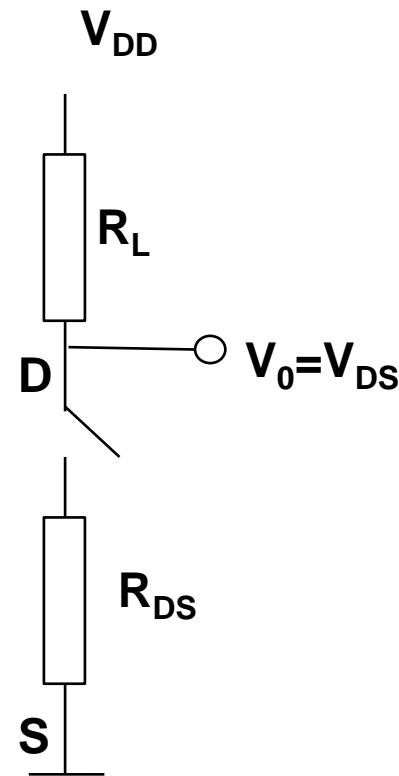
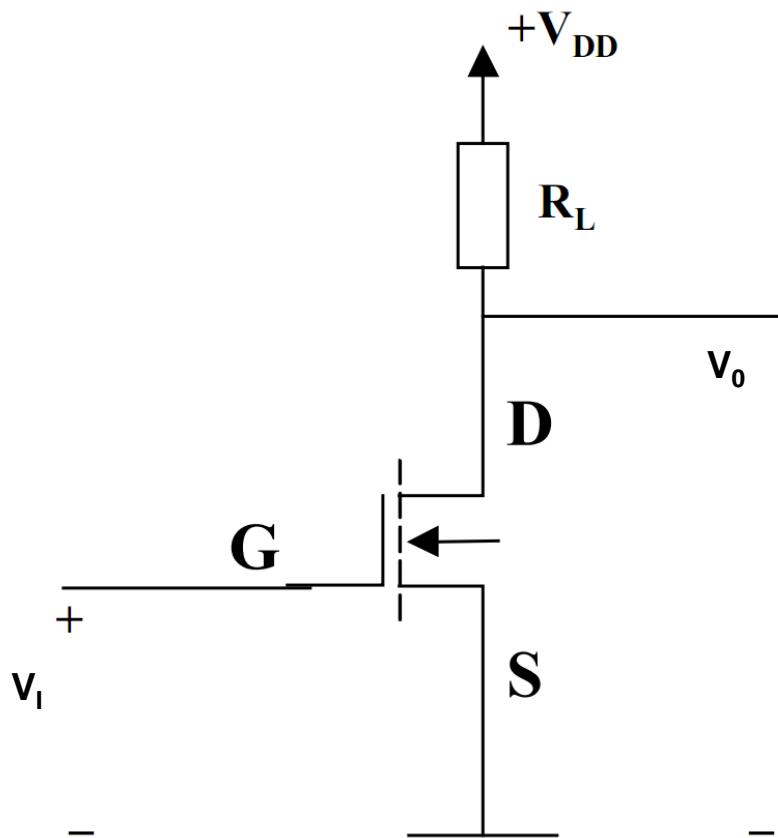
MOS → CONDUCE

$$V_0 = V_{DD} - I_{DS} \times R_L$$

I_{DS} Óhmico o Saturado

Resolver desigualdad

INVERSOR NMOS

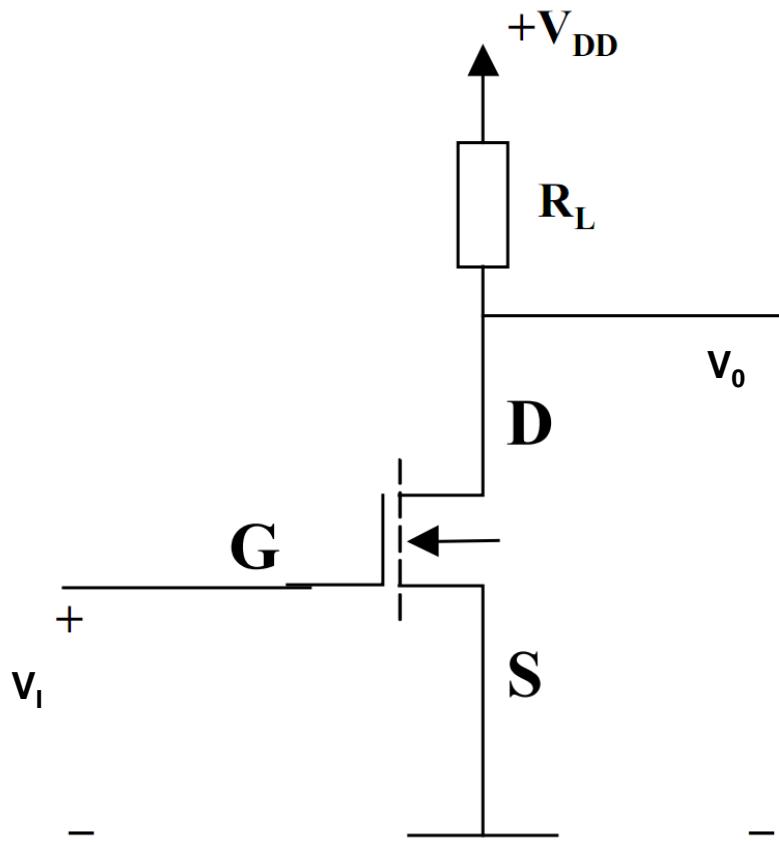


Para $V_i \leq V_{TH}$

MOS no conduce → llave abierta

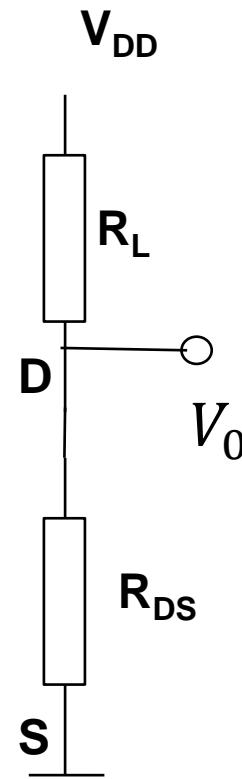
$$V_o = V_{DD} \rightarrow V_{HMAX} = V_{DD}$$

INVERSOR NMOS



Para $V_{TH} \leq V_I$

Para $V_I = V_{DD}$ si el MOS esta en zona óhmica



MOS conduce \rightarrow llave cerrada

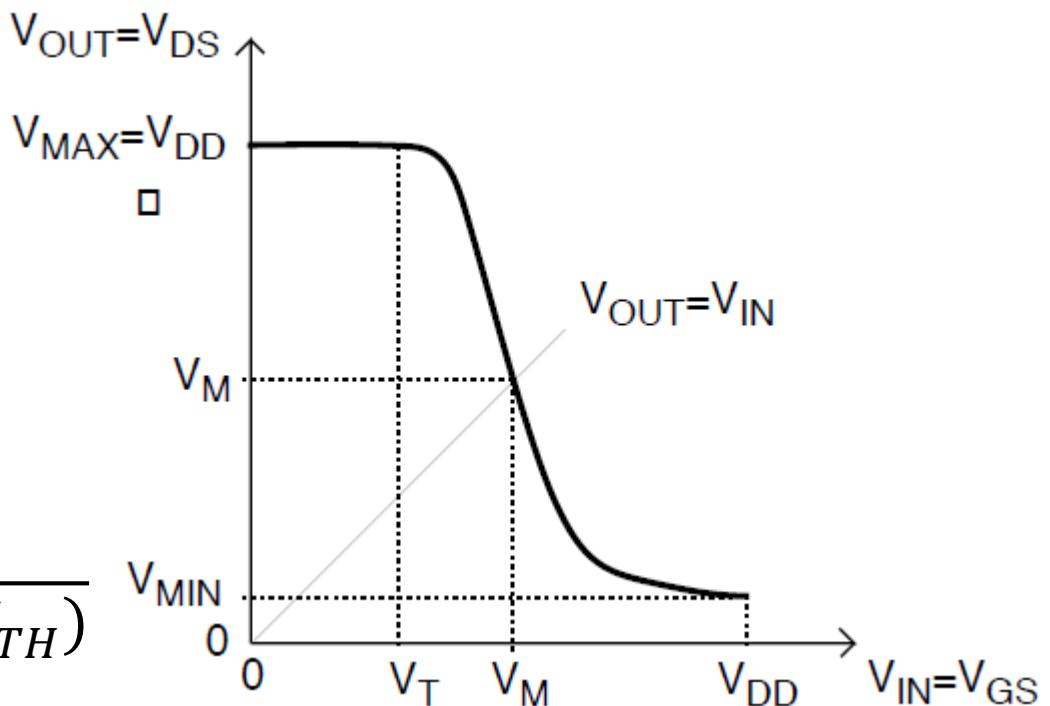
$$V_0 = V_{DD} \frac{R_{DS}}{R_{DS} + R_L}$$

$$R_{DS} = \frac{1}{\beta(V_{DD} - V_{TH})}$$

INVERSOR NMOS

$$V_{MAX} = V_{DD}$$

$$V_{MIN} = \frac{V_{DD}}{1 + R_L \beta (V_{DD} - V_{TH})}$$



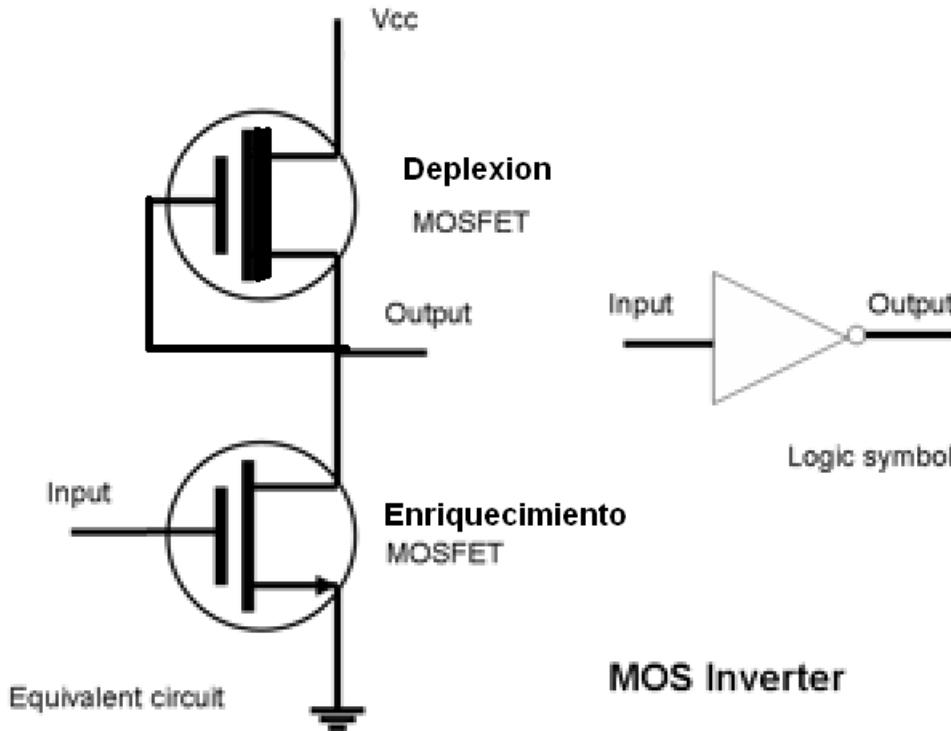
- Para que el nivel de salida bajo sea próximo a cero

$$V_{MIN} = V_{DD} \frac{R_{DS}}{R_{DS} + R_L}$$

$$R_L \gg R_{DS}$$

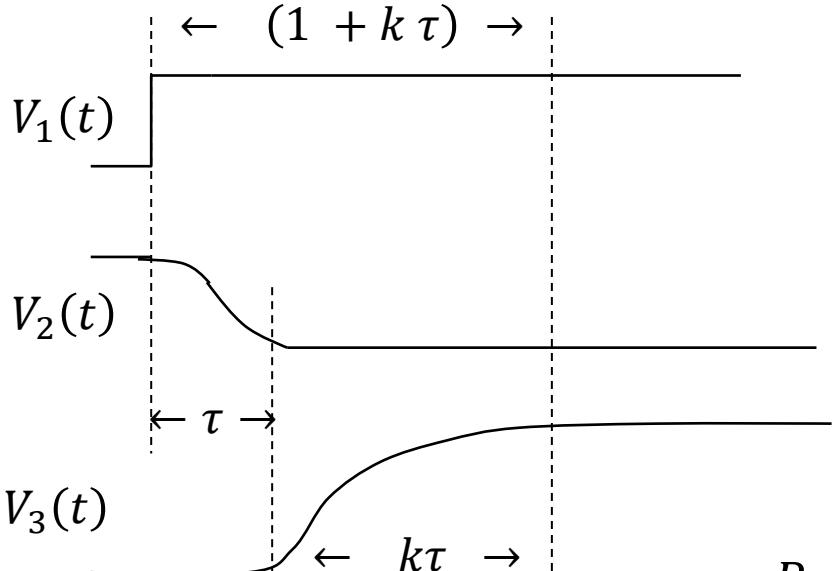
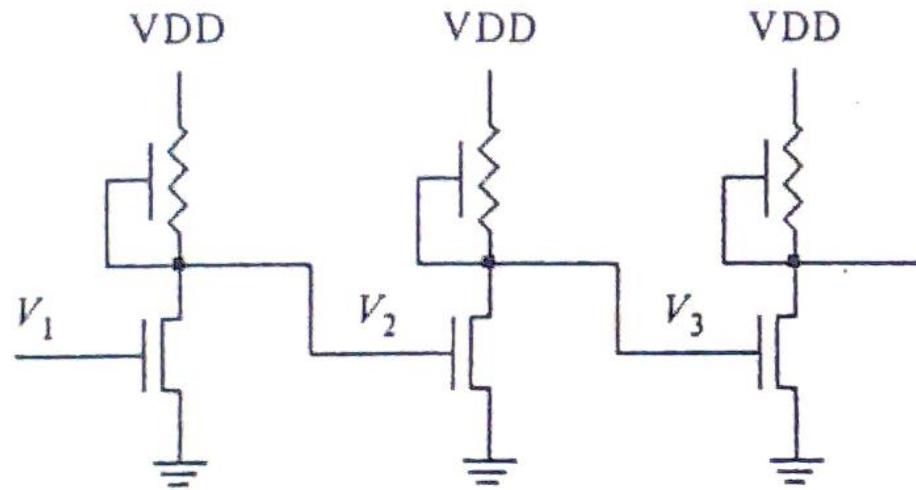
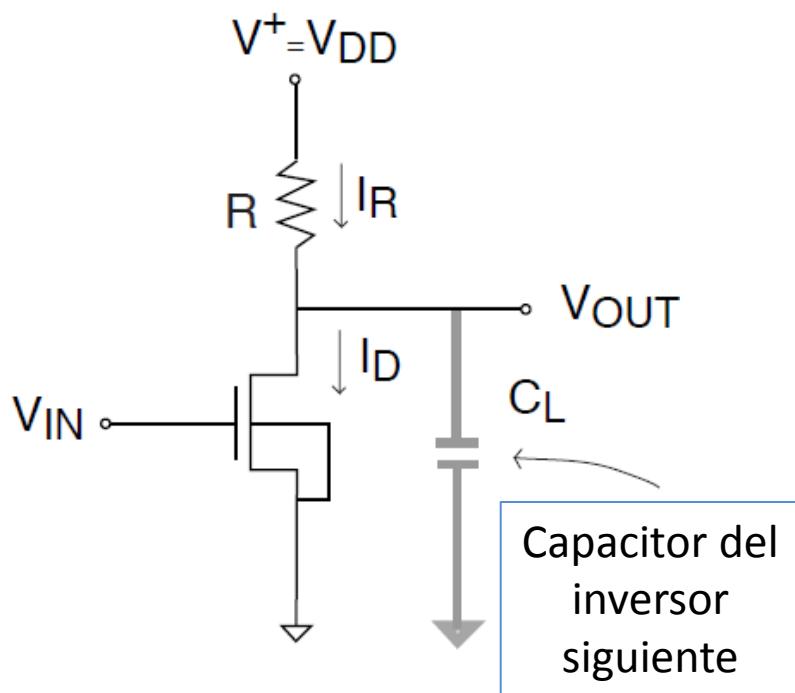
$$V_{MIN} \approx V_{DD} \frac{R_{DS}}{R_L}$$

INVERSOR NMOS



Circuito para obtener R_L de gran valor con poca área de silicio

Retardo del Inversor

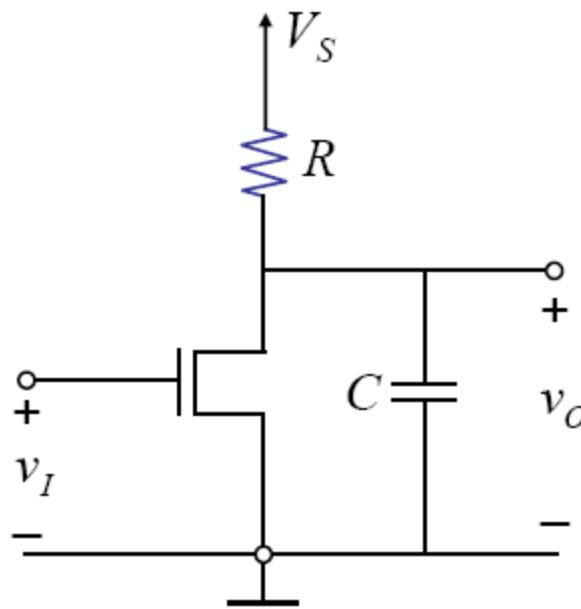


$$\tau = R_{DS} \times C_L$$

$$k = \frac{R_L}{R_{DS}}$$

Energía y potencia

Estudie la disipación de energía en las puertas del MOSFET



C : capacidad de cableado y
 C_{GS} de la puerta siguiente

Determinemos:

- la potencia de reserva
- la potencia activa

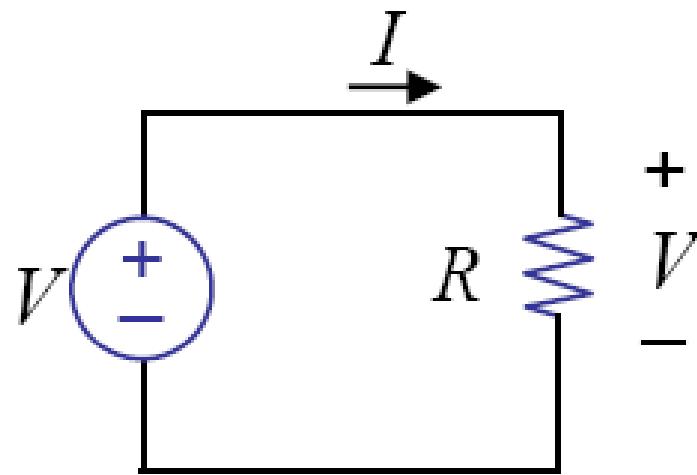
¿Por qué preocuparnos por la energía?



Hoy:

- ¿Cuánto durará la batería?
en modo de reserva
en uso activo
- ¿Se recalentará el chip y se autodestruirá?

Ejemplo 1:

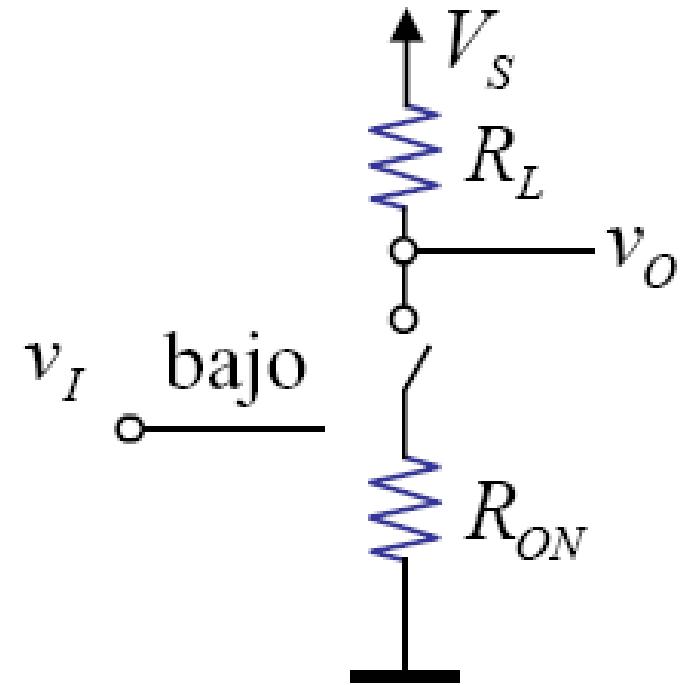
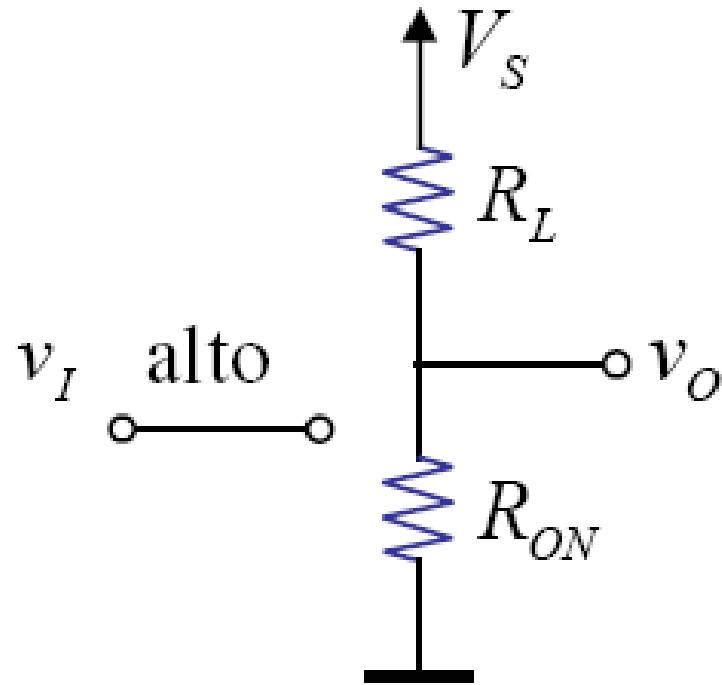


$$\text{Potencia, } P = VI = \frac{V^2}{R}$$

Energía disipada en tiempo T

$$E = VIT$$

Para nuestra puerta:

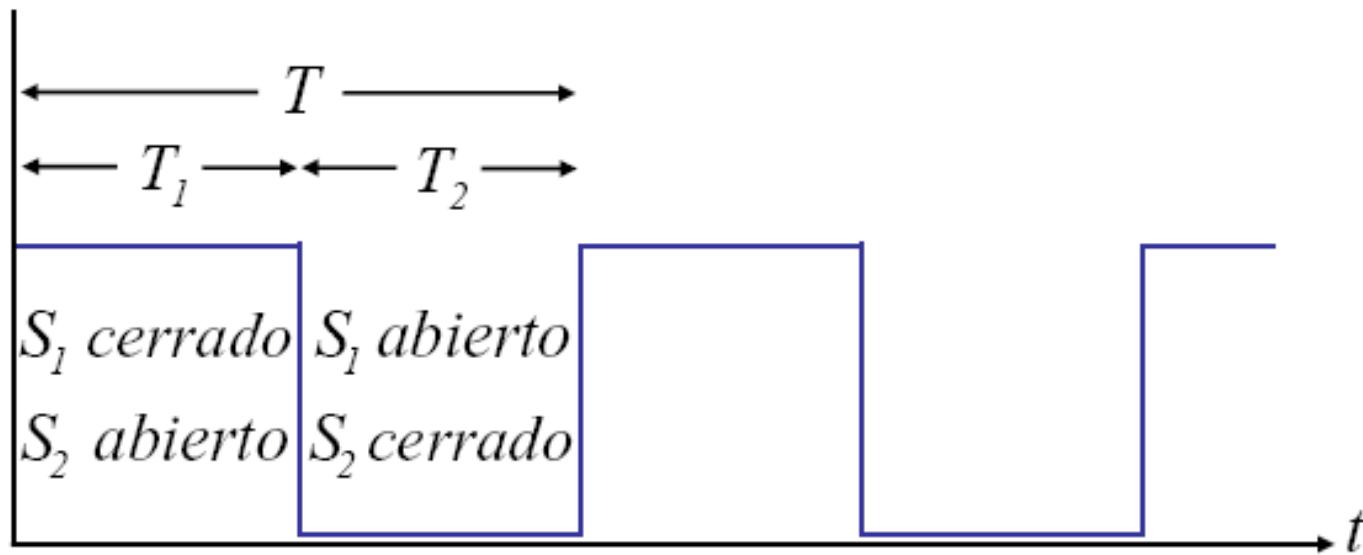
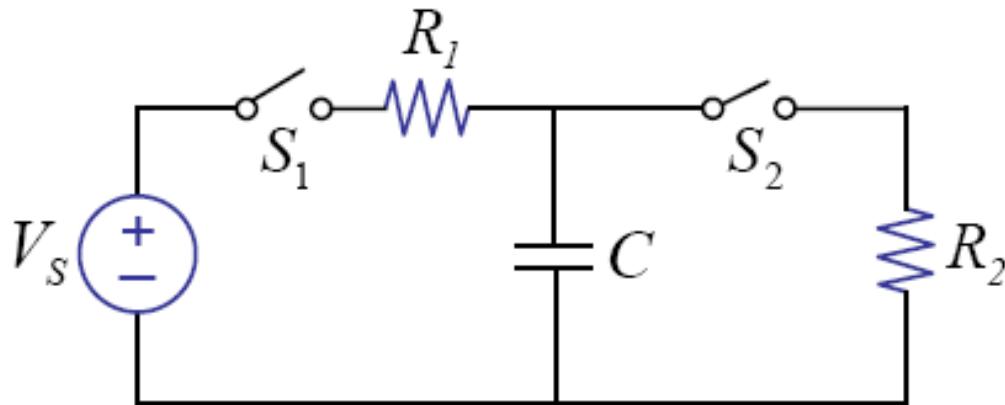


$$P = \frac{V_S^2}{R_L + R_{ON}} \quad \star$$

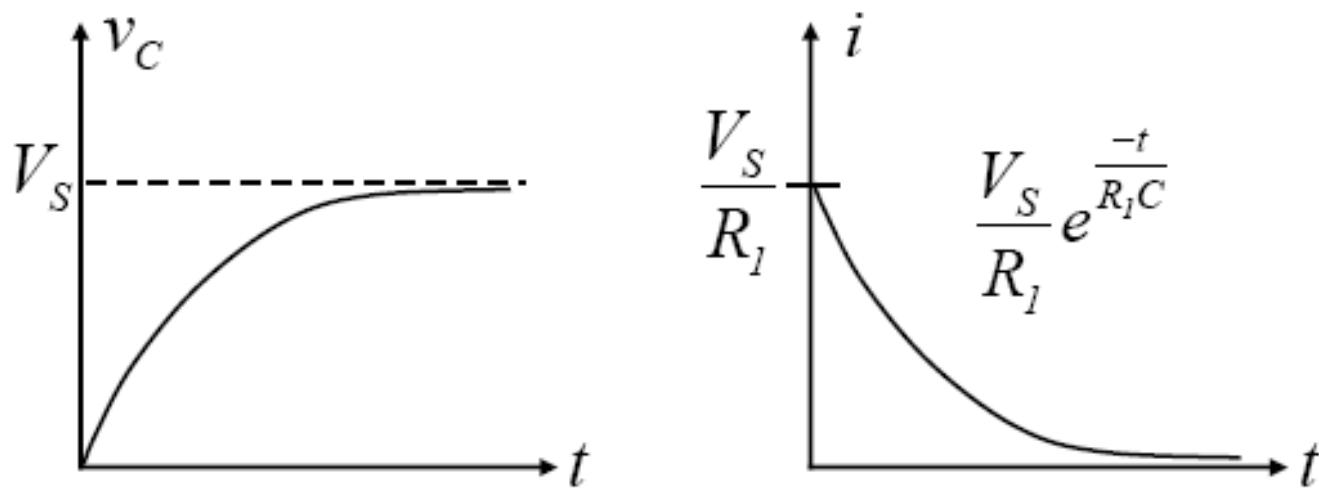
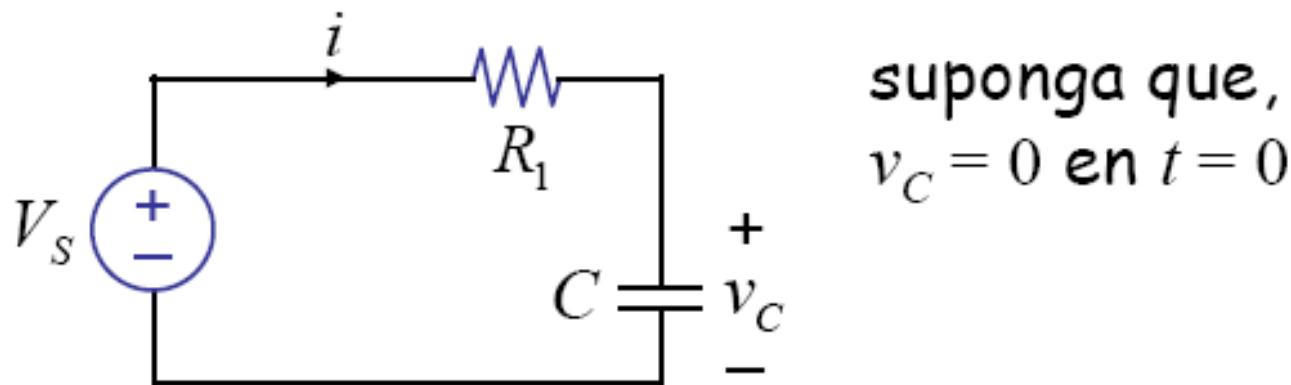
$$P = 0$$

Ejemplo 2:

Considere:



T_1 : S_1 cerrado, S_2 abierto



Energía total que proporciona una fuente durante T_I

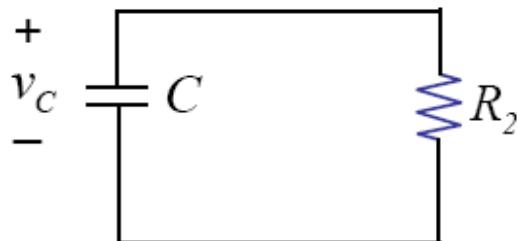
$$\begin{aligned} E &= \int_0^{T_I} V_S i \, dt \\ &= \int_0^{T_I} \frac{V_S^2}{R_I} e^{\frac{-t}{R_I C}} dt \\ &= -\frac{V_S^2}{R_I} R_I C e^{\frac{-t}{R_I C}} \Big|_0^{T_I} \end{aligned}$$

$$= C V_S^2 \left(1 - e^{\frac{-T_I}{R_I C}} \right)$$

$\approx C V_S^2$ si $T_I \gg R_I C$
es decir, si esperamos lo suficiente

$$\left. \begin{aligned} \frac{1}{2} C V_S^2 &\text{ almacenado en } C, \\ E_I = \frac{1}{2} C V_S^2 &\text{ disipado en } R_I \end{aligned} \right\} \begin{array}{l} \text{Independiente} \\ \text{de } R \end{array}$$

T_2 : S_2 cerrado, S_1 abierto



En un principio, $v_C = V_S$ (recuerde $T_1 \gg R_1 C$)

Por lo tanto, inicialmente,

$$\text{energía almacenada en condensador} = \frac{1}{2} C V_S^2$$

Suponga que $T_2 \gg R_2 C$

Por tanto, el condensador se descarga ~completamente en T_2

Por tanto, la energía disipada en R_2 durante T_2 ,

$$E_2 = \frac{1}{2} C V_S^2$$

E_1, E_2 independiente de R_2

Juntando los dos:

Energía disipada en cada ciclo,

$$E = E_1 + E_2$$

$$= \frac{1}{2} C V_s^2 + \frac{1}{2} C V_s^2$$

$E = C V_s^2$ energía disipada en
la carga y descarga de C

Supone que C se carga y se descarga completamente.

Potencia media,

$$\bar{P} = \frac{E}{T}$$

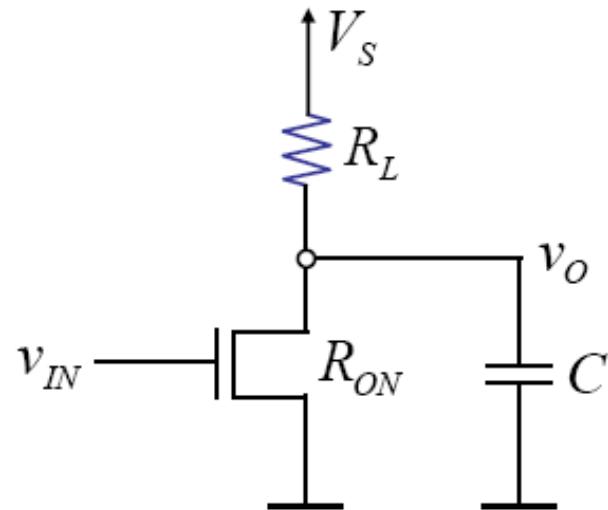
$$= \frac{CV_s^2}{T}$$

$$= CV_s^2 f$$

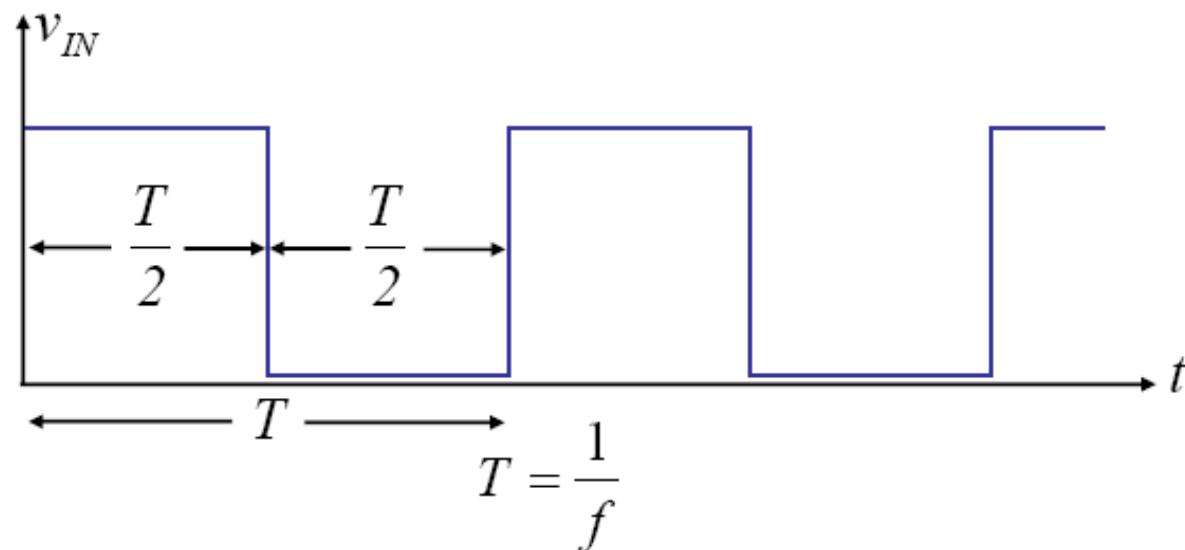


frecuencia $f = \frac{1}{T}$

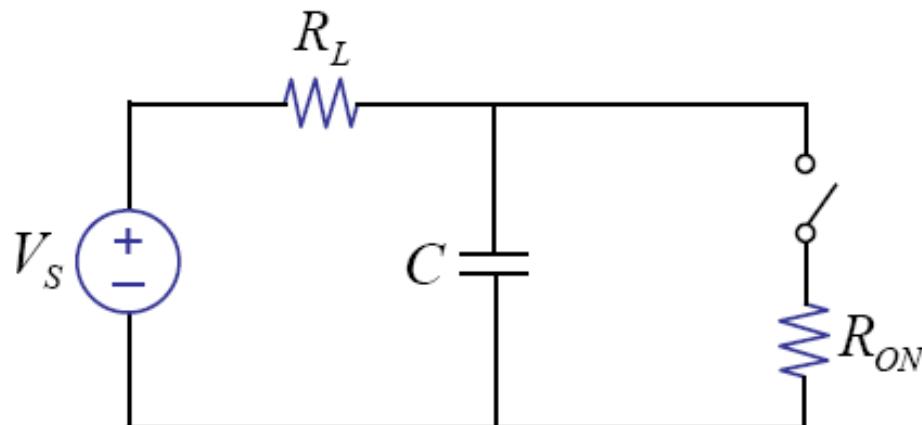
Volvemos a nuestro inversor —



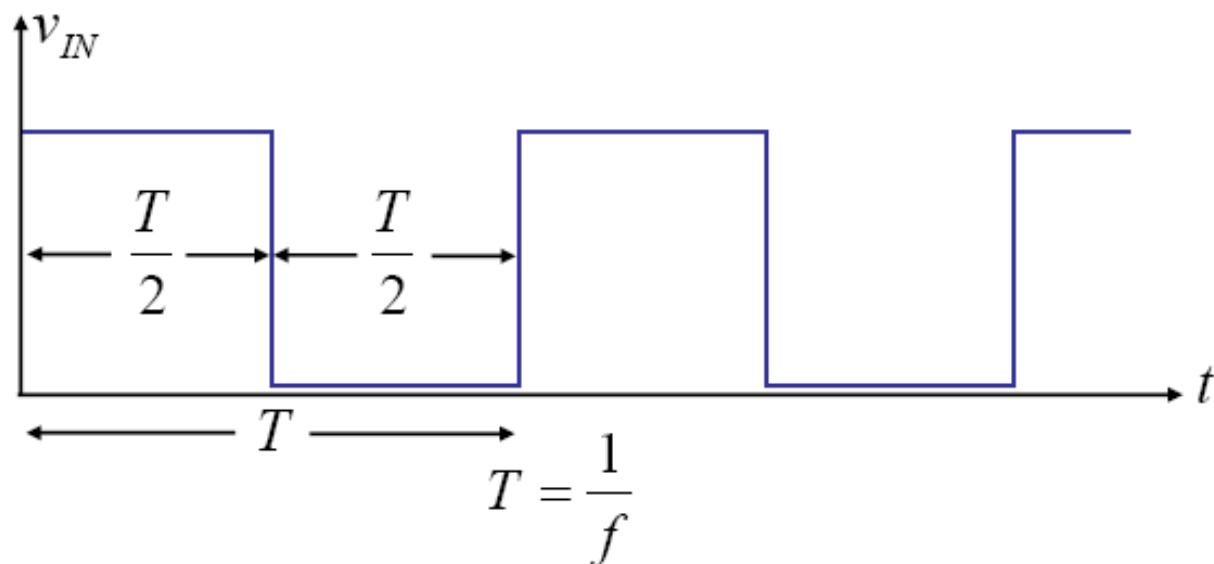
¿Qué es \bar{P} para la entrada siguiente?



Circuito equivalente



¿Qué es \bar{P} para la entrada siguiente?



¿Qué es \bar{P} para la puerta?

Cuando $R_L \gg R_{ON}$

$$\bar{P} = \frac{V_s^2}{2R_L} + CV_s^2 f$$

En modo de reserva,
se puede suponer que
la mitad de las puertas
en un chip están ON.

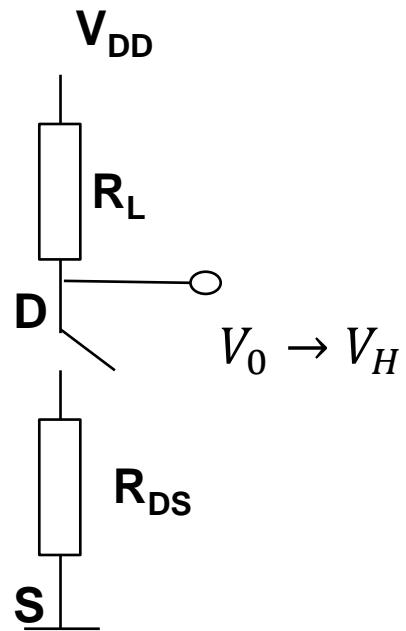
Por tanto, $\bar{P}_{ESTÁTICO}$ por

puerta es $\frac{V_s^2}{2R_L}$.

Está relacionado con la
potencia de reserva.

En modo de reserva,
 $f \rightarrow 0$,
por lo que la potencia
dinámica es 0

Potencia



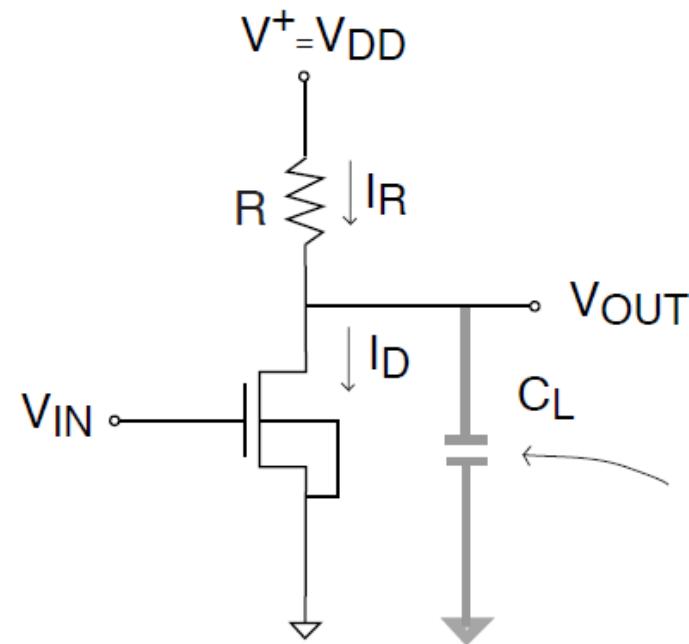
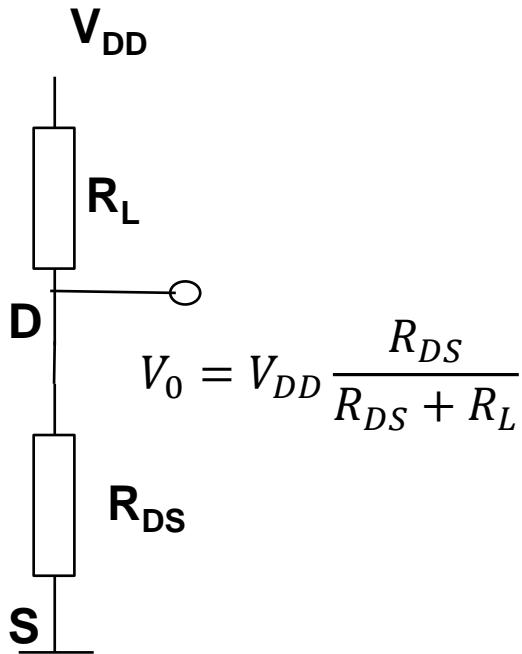
$$P_{E1} = 0$$

$$P_E = \frac{P_{E1} + P_{E2}}{2}$$

$$P_{E2} = \frac{V_{DD}^2}{R_{DS} + R_L}$$

$$P_E = \frac{1}{2} \frac{V_{DD}^2}{(R_{DS} + R_L)}$$

$$P = P_E + P_D$$



$$P_D = C_L V_{DD}^2 \times f$$

$$P \approx \frac{V_{DD}^2}{2R_L} + C_L V_{DD}^2 \times f$$

Algunos números...

Un chip con 10^6 puertas cronometrando
a 100 MHZ

$$C = 1fF$$

$$R_L = 10k\Omega$$

$$f = 100 \times 10^6$$

$$V_S = 5V$$

$$\overline{P} = 10^6 \left[\frac{25}{2 \times 10^4} + 10^{-15} \times 25 \times 100 \times 10^6 \right]$$

$$= 10^6 [1.25 \text{ milivatios} + 2.5 \text{ microvativos}]$$

i problema!

debe deshacerse de esto

1.25KW!

2.5W
no está mal

$$\alpha V_S^2$$

$$\alpha f$$

reduzca V_S

$$5V \rightarrow 1V$$

$$2.5W \rightarrow 150mW$$

INVERSOR NMOS

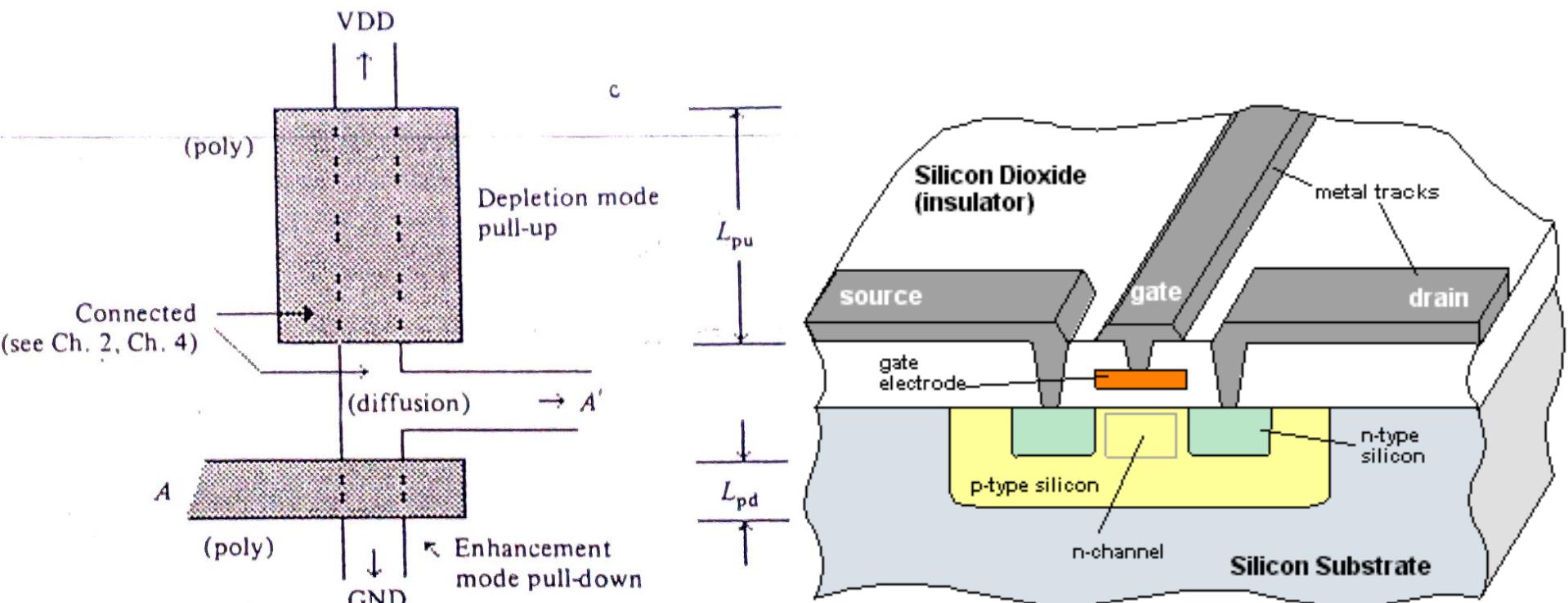


Fig. 1.8 Basic inverter layout.

Compuerta NAND

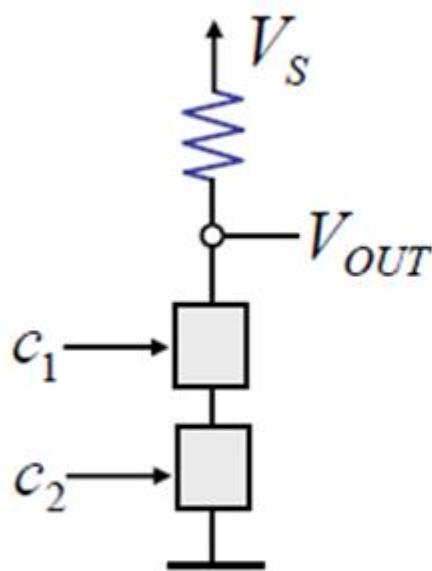
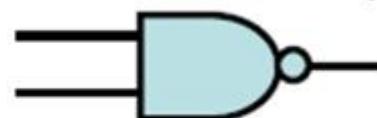
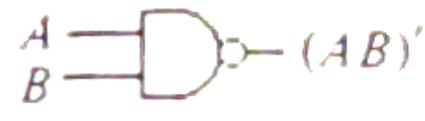
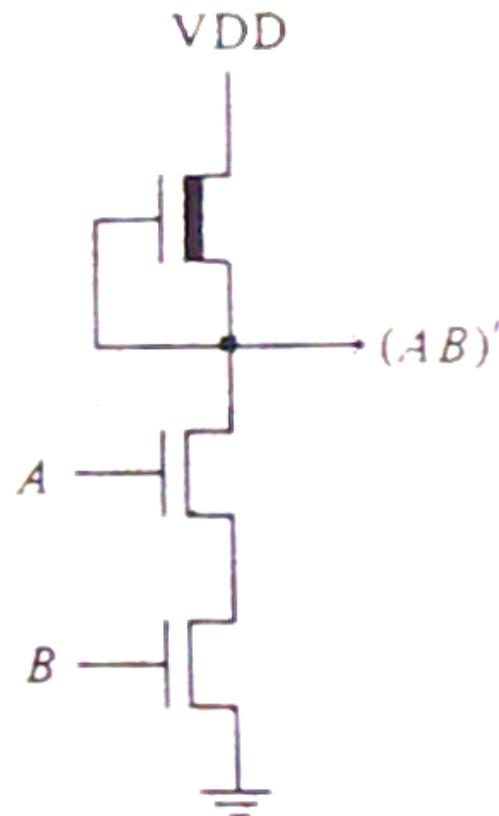
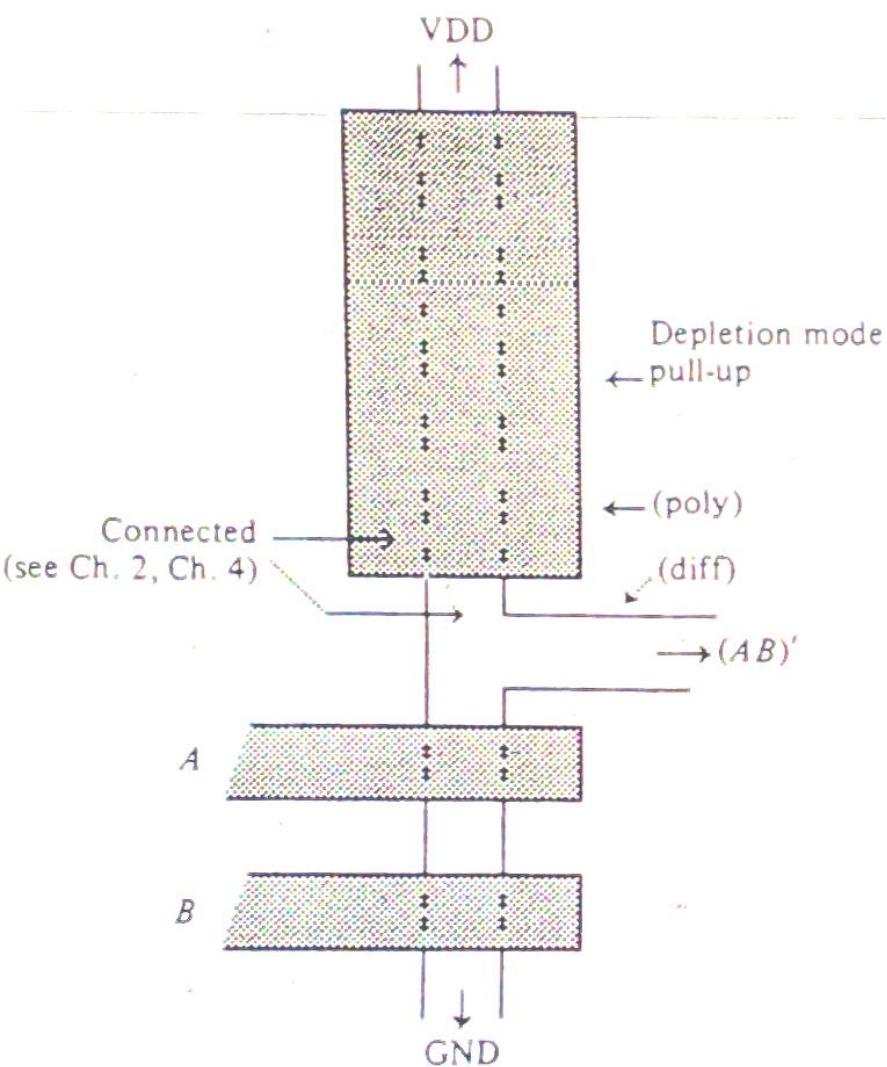


Tabla de verdad para



c_1	c_2	V_O
0	0	1
0	1	1
1	0	1
1	1	0

Compuerta NAND



A	B	$(AB)'$
0	0	1
0	1	1
1	0	1
1	1	0

Compuerta NOR

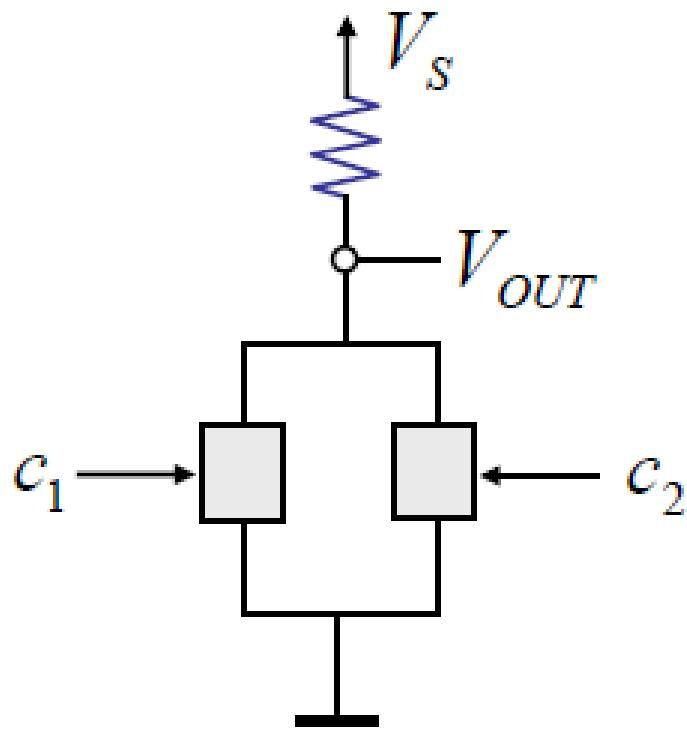
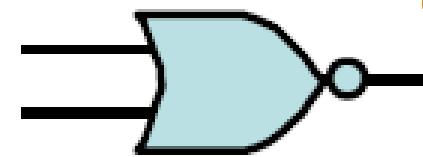
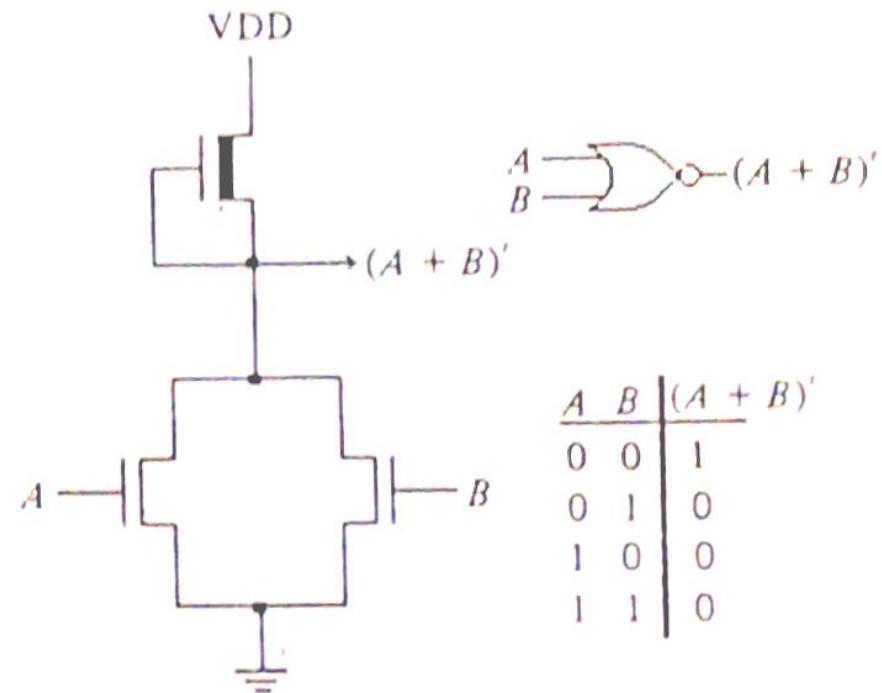
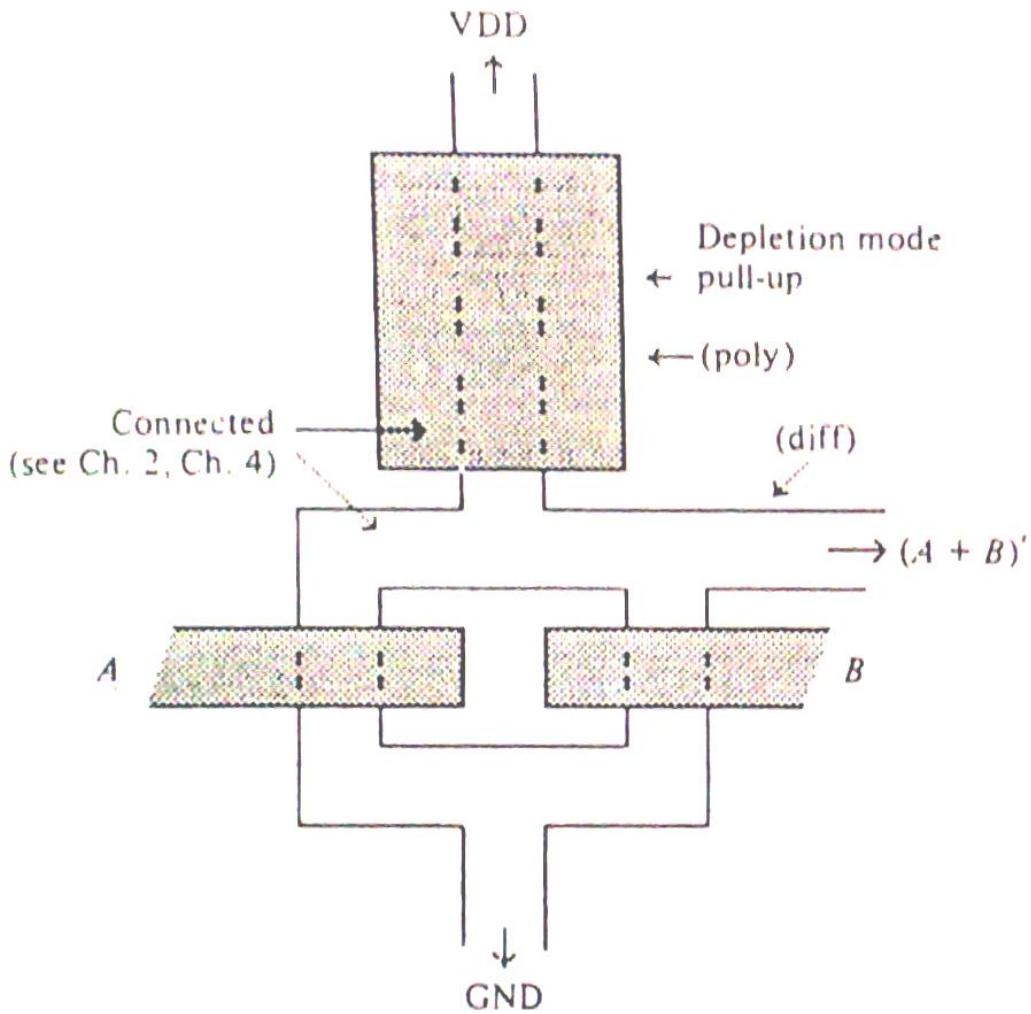


Tabla de verdad para

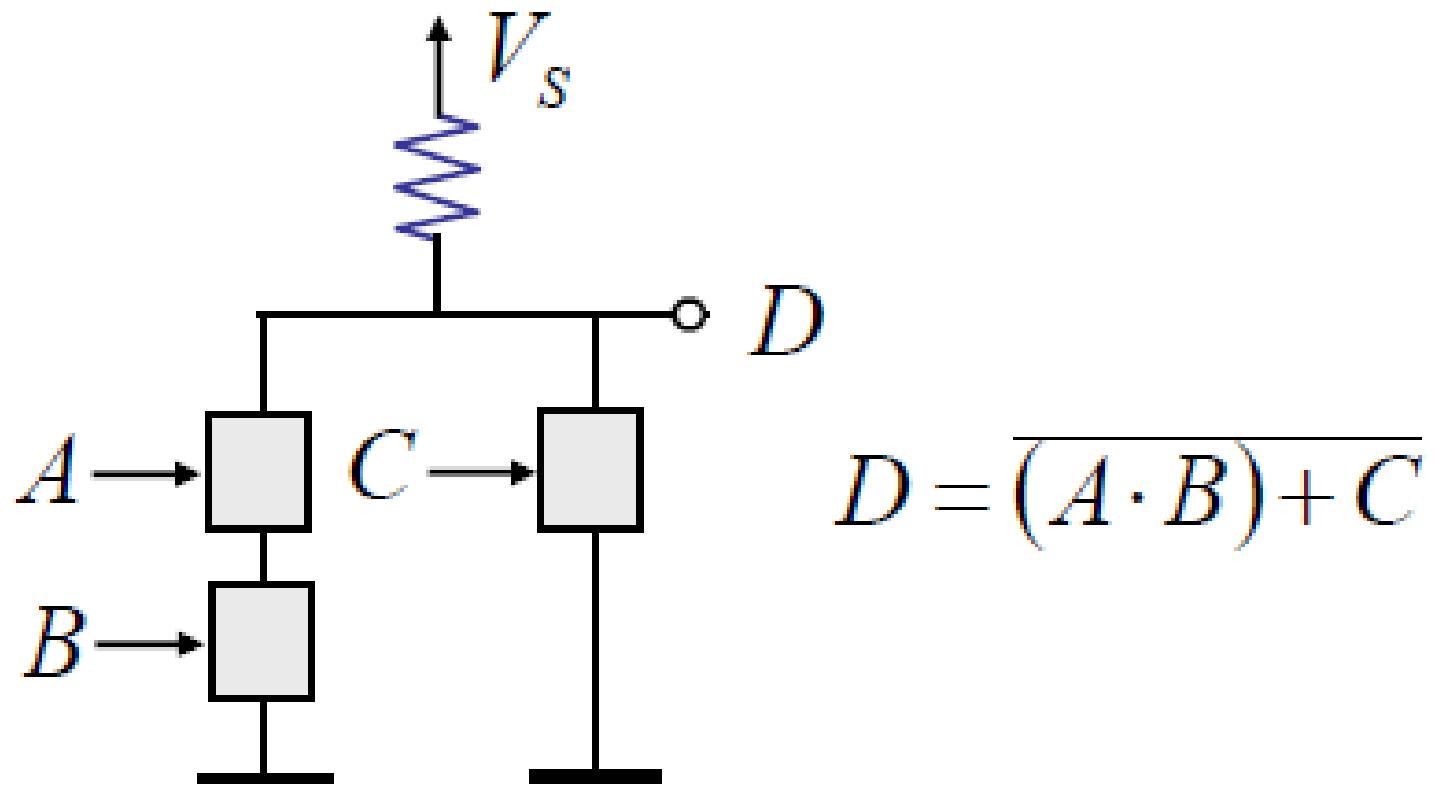


c_1	c_2	V_O
0	0	1
0	1	0
1	0	0
1	1	0

Compuerta NOR



Función LÓGICA



Efectos debido a la miniaturización de los circuitos MOS

$$\tau \propto L^2/V$$

$$\tau' / \tau = [(L/\alpha)^2 / (V/\alpha)] / (L^2/V)$$

$$\tau' = \tau / \alpha$$

$$C \propto LW/D$$

$$C' / C = [(L/\alpha)(W/\alpha) / (D/\alpha)] / (LW/D)$$

$$C' = C / \alpha$$

$$I \propto WV^2/LD$$

$$I' / I = [(WV^2/\alpha^3) / (LD/\alpha^2)] / (WV^2/LD)$$

$$I' = I / \alpha$$

$$P_{SW} \propto CV^2/\tau \propto WV^3/DL$$

$$P'_{SW} = P_{SW} / \alpha^2$$

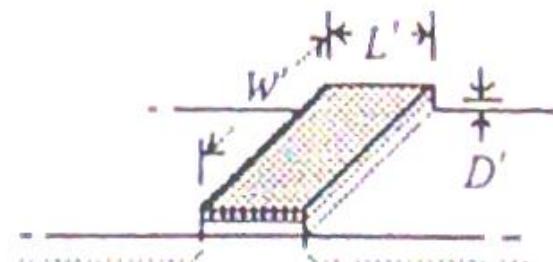
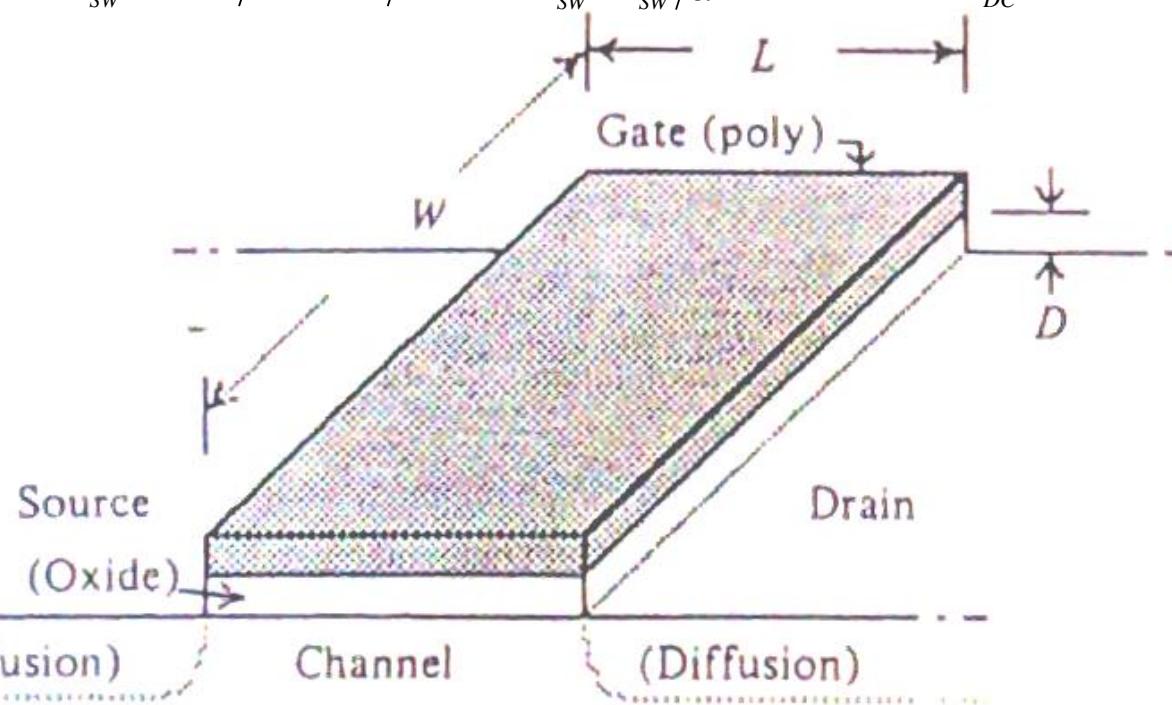
$$P_{DC} = IV$$

$$P'_{DC} = P_{DC} / \alpha^2$$

$$W' = W / \alpha$$

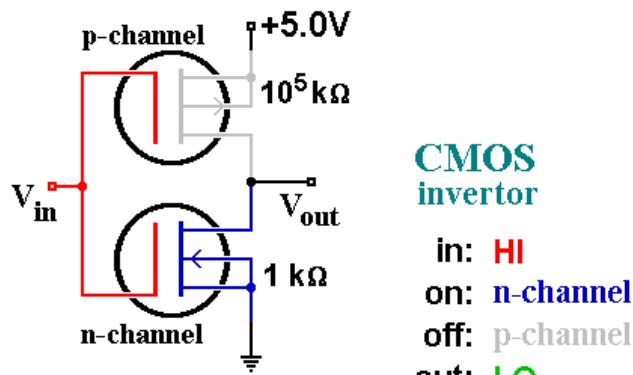
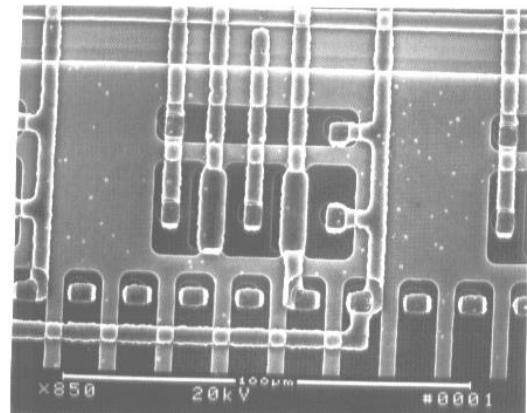
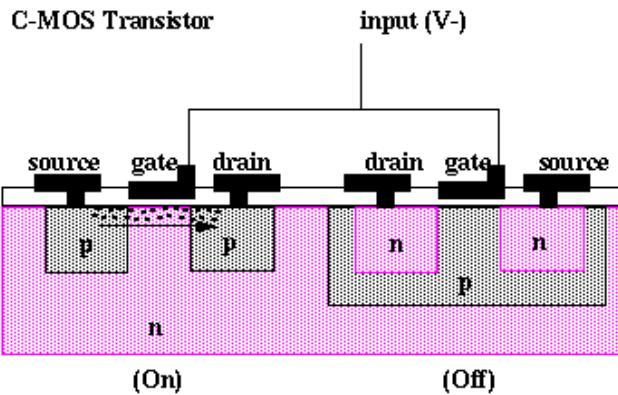
$$L' = L / \alpha$$

$$D' = D / \alpha$$

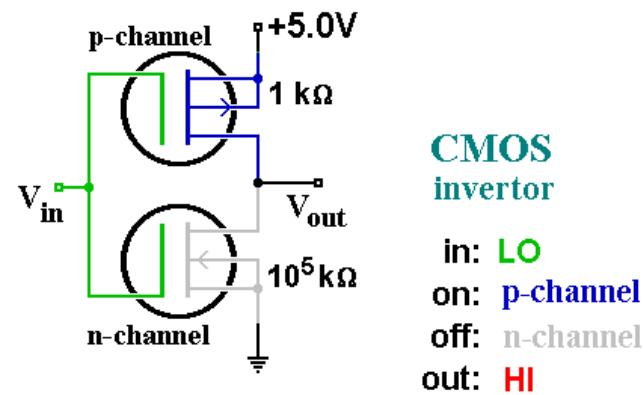


Aplicaciones: Circuitos Lógicos

Tecnología CMOS



CMOS inverter
in: HI
on: n-channel
off: p-channel
out: LO



CMOS inverter
in: LO
on: p-channel
off: n-channel
out: HI

Aplicaciones: Memorias RAM

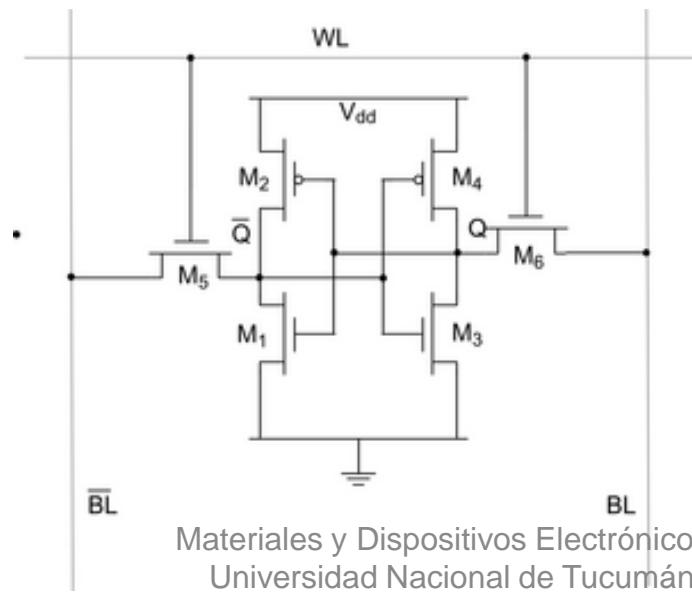
DRAM

Se almacena un “1” en la celda cargando el condensador mediante una V_G en fila y V_D en bit

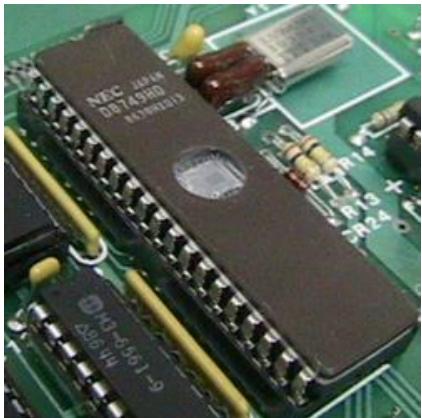
La lectura se hace aplicando V_G en fila y midiendo la corriente en la línea bit

La lectura es un proceso destructivo. Hay que restaurar el valor leído

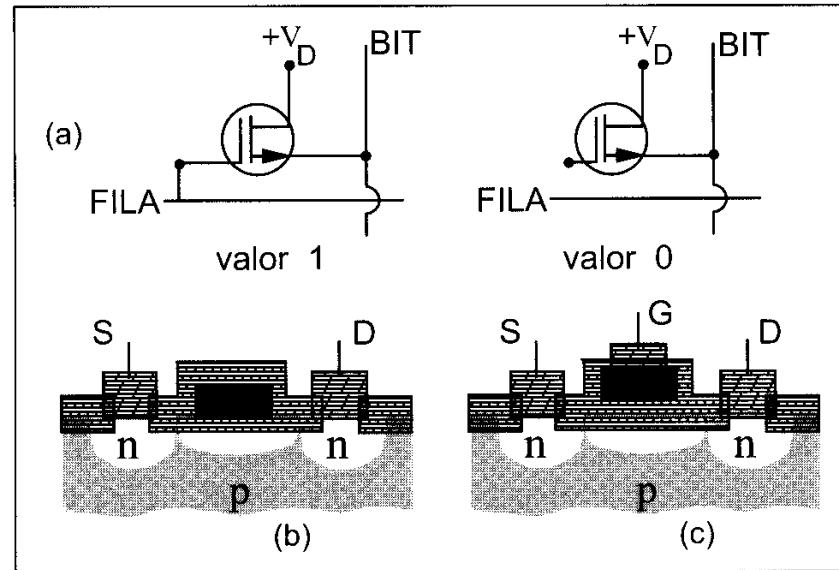
SRAM



Aplicaciones: Memorias ROM

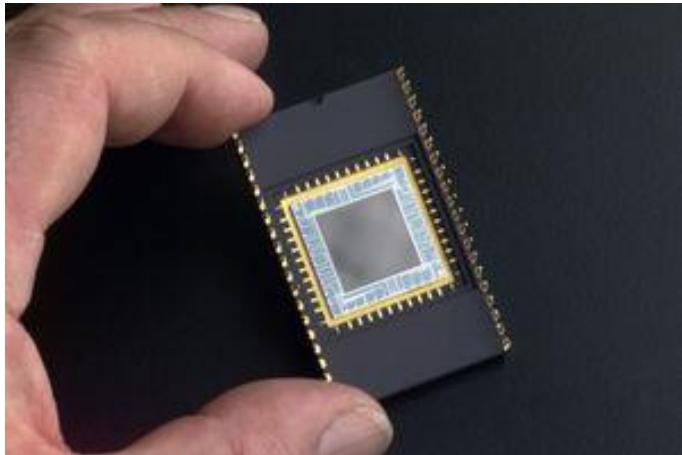


EPROM

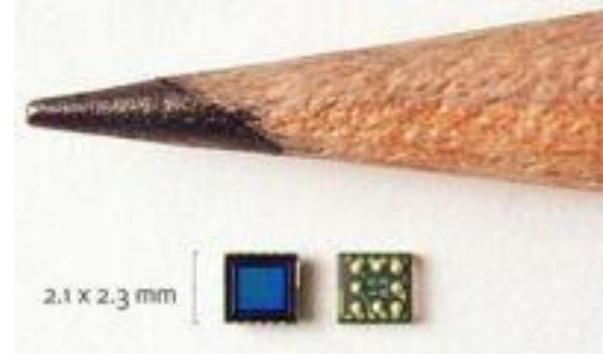
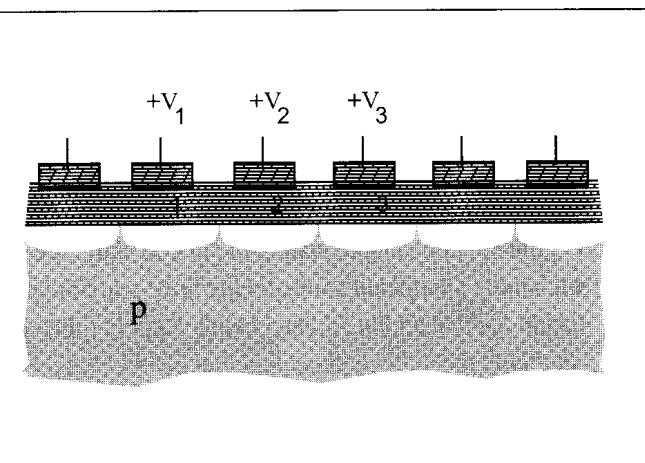


MOSFET ROM

Aplicaciones: CCD



CCD



CMOS sensor

